

## Current-Limited, Power-Distribution Switches

Check for Samples: [TPS20xxC](#), [TPS20xxC-2](#)

### FEATURES

- Single Power Switch Family
- Pin for Pin with Existing [TI Switch Portfolio](#)
- Rated currents of 0.5 A, 1 A, 1.5 A, 2 A
- $\pm 20\%$  Accurate, Fixed, Constant Current Limit
- Fast Over-Current Response – 2  $\mu$ s
- Deglitched Fault Reporting
- Selected Parts with (TPS20xxC) and without (TPS20xxC-2) Output Discharge
- Reverse Current Blocking
- Built-in Softstart
- Ambient Temperature Range:  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$
- UL Listed and CB-File No. E169910 (See [Table 1](#))

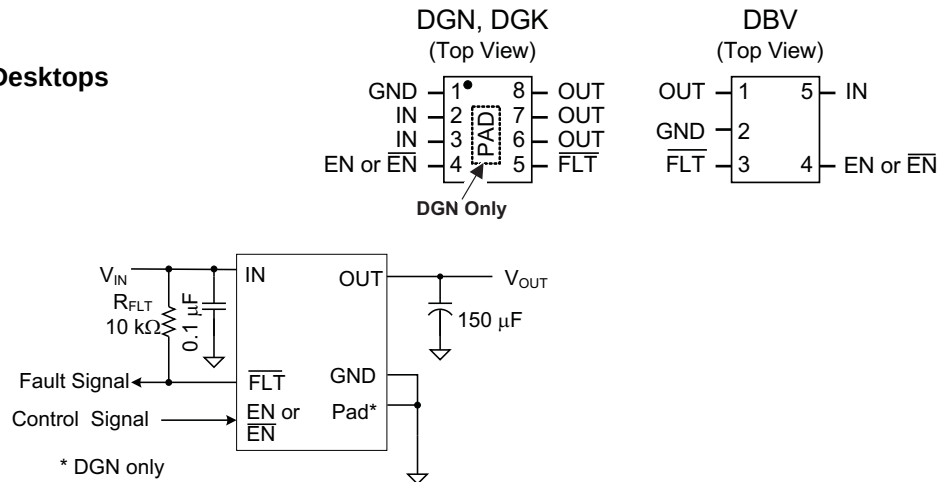
### APPLICATIONS

- USB Ports/Hubs, Laptops, Desktops
- High-Definition Digital TVs
- Set Top Boxes
- Short-Circuit Protection

### DESCRIPTION

The TPS20xxC and TPS20xxC-2 power-distribution switch family is intended for applications such as USB where heavy capacitive loads and short-circuits are likely to be encountered. This family offers multiple devices with fixed current-limit thresholds for applications between 0.5 A and 2 A.

The TPS20xxC and TPS20xxC-2 family limits the output current to a safe level by operating in a constant-current mode when the output load exceeds the current-limit threshold. This provides a predictable fault current under all conditions. The fast overload response time eases the burden on the main 5 V supply to provide regulated power when the output is shorted. The power-switch rise and fall times are controlled to minimize current surges during turn-on and turn-off.



**Figure 1. Typical Application**

**Table 1. DEVICES<sup>(1)</sup>**

| MAXIMUM OPERATING CURRENT | DEVICES          | STATUS                                          |                                  |                                                 |
|---------------------------|------------------|-------------------------------------------------|----------------------------------|-------------------------------------------------|
|                           |                  | MSOP-8 (PowerPad™)                              | SOT23-5                          | MSOP-8                                          |
| 0.5                       | TPS2041C and 51C | —                                               | Active and Active <sup>(2)</sup> | —                                               |
| 1                         | TPS2061C and 65C | Active and Active <sup>(2)</sup>                | Active and Active <sup>(2)</sup> | —                                               |
| 1                         | TPS2065C-2       | Active                                          | Active                           | —                                               |
| 1.5                       | TPS2068C and 69C | Active and Active <sup>(2)</sup>                | — and Active                     | —                                               |
| 1.5                       | TPS2069C-2       | Active                                          | —                                | —                                               |
| 2                         | TPS2000C and 01C | Active <sup>(2)</sup> and Active <sup>(2)</sup> | —                                | Active <sup>(2)</sup> and Active <sup>(2)</sup> |

(1) For more details, see the [DEVICE INFORMATION](#) table.

(2) UL listed and CB complete.



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# TPS20xxC, TPS20xxC-2

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## DEVICE INFORMATION<sup>(1)</sup>

| MAXIMUM OPERATING CURRENT | OUTPUT DISCHARGE | ENABLE | BASE PART NUMBER | PACKAGED DEVICE AND MARKING <sup>(2)</sup> |               |              |
|---------------------------|------------------|--------|------------------|--------------------------------------------|---------------|--------------|
|                           |                  |        |                  | MSOP-8 (DGN) PowerPAD™                     | SOT23-5 (DBV) | MSOP-8 (DGK) |
| 0.5                       | Y                | Low    | TPS2041C         | –                                          | PYJI          | –            |
| 0.5                       | Y                | High   | TPS2051C         | –                                          | VBYQ          | –            |
| 1                         | Y                | Low    | TPS2061C         | PXMI                                       | PXLI          | –            |
| 1                         | Y                | High   | TPS2065C         | VCAQ                                       | VCAQ          | –            |
| 1                         | N                | High   | TPS2065C-2       | PYRI                                       | PYQI          | –            |
| 1.5                       | Y                | Low    | TPS2068C         | PXNI                                       | –             | –            |
| 1.5                       | Y                | High   | TPS2069C         | VBUQ                                       | PXKI          | –            |
| 1.5                       | N                | High   | TPS2069C-2       | PYSI                                       | –             | –            |
| 2                         | Y                | Low    | TPS2000C         | BCMS                                       | –             | PXFI         |
| 2                         | Y                | High   | TPS2001C         | VBWQ                                       | –             | PXGI         |

(1) For the most current packaging and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

(2) "–" indicates the device is not available in this package.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)(2)</sup>

|                                                                                                 |                                             | VALUE              |     | UNIT |
|-------------------------------------------------------------------------------------------------|---------------------------------------------|--------------------|-----|------|
|                                                                                                 |                                             | MIN                | MAX |      |
| Voltage range on IN, OUT, EN or $\overline{\text{EN}}$ , $\overline{\text{FLT}}$ <sup>(3)</sup> |                                             | –0.3               | 6   | V    |
| Voltage range from IN to OUT                                                                    |                                             | –6                 | 6   | V    |
| Maximum junction temperature, T <sub>J</sub>                                                    |                                             | Internally Limited |     |      |
| Electrostatic Discharge                                                                         | HBM                                         | 2                  |     | kV   |
|                                                                                                 | CDM                                         | 500                |     | V    |
|                                                                                                 | IEC 61000-4-2, Contact / Air <sup>(4)</sup> | 8                  | 15  | kV   |

(1) Absolute maximum ratings apply over recommended junction temperature range.

(2) Voltages are with respect to GND unless otherwise noted.

(3) See the [Input and Output Capacitance](#) section.

(4) V<sub>OUT</sub> was surged on a pcb with input and output bypassing per [Figure 1](#) (except input capacitor was 22 µF) with no device failures.

## THERMAL INFORMATION

| THERMAL METRIC <sup>(1)</sup><br>(See DEVICE INFORMATION table.) |                                                                            | 0.5 A or 1 A<br>Rated | 1.5 A or 2 A<br>Rated | 0.5 A or 1 A<br>Rated | 1.5 A or 2 A<br>Rated | 2 A<br>Rated | UNITS |
|------------------------------------------------------------------|----------------------------------------------------------------------------|-----------------------|-----------------------|-----------------------|-----------------------|--------------|-------|
|                                                                  |                                                                            | DBV                   | DBV                   | DGN                   | DGN                   | DGK          |       |
|                                                                  |                                                                            | 5 PINS                | 5 PINS                | 8 PINS                | 8 PINS                | 8 PINS       |       |
| θ <sub>JA</sub>                                                  | Junction-to-ambient thermal resistance                                     | 224.9                 | 220.4                 | 72.1                  | 67.1                  | 205.5        | °C/W  |
| θ <sub>JCTop</sub>                                               | Junction-to-case (top) thermal resistance                                  | 95.2                  | 89.7                  | 87.3                  | 80.8                  | 94.3         |       |
| θ <sub>JB</sub>                                                  | Junction-to-board thermal resistance                                       | 51.4                  | 46.9                  | 42.2                  | 37.2                  | 126.9        |       |
| ψ <sub>JT</sub>                                                  | Junction-to-top characterization parameter                                 | 6.6                   | 5.2                   | 7.3                   | 5.6                   | 24.7         |       |
| ψ <sub>JB</sub>                                                  | Junction-to-board characterization parameter                               | 50.3                  | 46.2                  | 42.0                  | 36.9                  | 125.2        |       |
| θ <sub>JCbot</sub>                                               | Junction-to-case (bottom) thermal resistance                               | N/A                   | N/A                   | 39.2                  | 32.1                  | N/A          |       |
| θ <sub>JA</sub> Custom                                           | See the <a href="#">Power Dissipation and Junction Temperature</a> section | 139.3                 | 134.9                 | 66.5                  | 61.3                  | 110.3        |       |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## RECOMMENDED OPERATING CONDITIONS

|           |                                                 | MIN                               | NOM | MAX | UNIT |
|-----------|-------------------------------------------------|-----------------------------------|-----|-----|------|
| $V_{IN}$  | Input voltage, IN                               | 4.5                               |     | 5.5 | V    |
| $V_{EN}$  | Input voltage, EN or $\overline{EN}$            | 0                                 |     | 5.5 | V    |
| $V_{IH}$  | High-level input voltage, EN or $\overline{EN}$ | 2                                 |     |     | V    |
| $V_{IL}$  | Low-level input voltage, EN or $\overline{EN}$  |                                   |     | 0.7 | V    |
| $I_{OUT}$ | Continuous output current, OUT <sup>(1)</sup>   | TPS2041C and TPS2051C             |     | 0.5 | A    |
|           |                                                 | TPS2061C, TPS2065C and TPS2065C-2 |     | 1   |      |
|           |                                                 | TPS2068C, TPS2069C and TPS2069C-2 |     | 1.5 |      |
|           |                                                 | TPS2000C and TPS2001C             |     | 2   |      |
| $T_J$     | Operating junction temperature                  | –40                               |     | 125 | °C   |
| $I_{FLT}$ | Sink current into $\overline{FLT}$              | 0                                 |     | 5   | mA   |

(1) Some package and current rating may request an ambient temperature derating of 85°C.

## ELECTRICAL CHARACTERISTICS: $T_J = T_A = 25^\circ\text{C}$ <sup>(1)</sup>

Unless otherwise noted:  $V_{IN} = 5\text{ V}$ ,  $V_{EN} = V_{IN}$  or  $V_{EN} = \text{GND}$ ,  $I_{OUT} = 0\text{ A}$ . See the 'Device Information' table for the rated current of each part number. Parametrics over a wider operational range are shown in the second 'Electrical Characteristics' table.

| PARAMETER                                                                     |                                                                                                                                         | TEST CONDITIONS <sup>(1)</sup> |      | MIN  | TYP  | MAX | UNIT |
|-------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|--------------------------------|------|------|------|-----|------|
| POWER SWITCH                                                                  |                                                                                                                                         |                                |      |      |      |     |      |
| R <sub>DS(on)</sub> Input – output resistance                                 | 0.5 A rated output, 25°C                                                                                                                | DBV                            |      | 97   | 110  | mΩ  |      |
|                                                                               | 0.5 A rated output,<br>–40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C                                                                | DBV                            |      | 96   | 130  | mΩ  |      |
|                                                                               | 1 A rated output, 25°C                                                                                                                  | DBV                            |      | 96   | 110  | mΩ  |      |
|                                                                               |                                                                                                                                         | DGN                            |      | 86   | 100  |     |      |
|                                                                               | 1 A rated output,<br>–40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C                                                                  | DBV                            |      | 96   | 130  | mΩ  |      |
|                                                                               |                                                                                                                                         | DGN                            |      | 86   | 120  |     |      |
|                                                                               | 1.5 A rated output, 25°C                                                                                                                | DBV                            |      | 76   | 91   | mΩ  |      |
|                                                                               |                                                                                                                                         | DGN                            |      | 69   | 84   | mΩ  |      |
|                                                                               | 1.5 A rated output,<br>–40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C                                                                | DBV                            |      | 76   | 106  | mΩ  |      |
|                                                                               |                                                                                                                                         | DGN                            |      | 69   | 98   | mΩ  |      |
|                                                                               | 2 A rated output, 25°C                                                                                                                  | DGN, DGK                       |      | 72   | 84   | mΩ  |      |
|                                                                               | 2 A rated output, –40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C                                                                     | DGN, DGK                       |      | 72   | 98   | mΩ  |      |
| CURRENT LIMIT                                                                 |                                                                                                                                         |                                |      |      |      |     |      |
| I <sub>OS</sub> <sup>(2)</sup> Current-limit,<br>See <a href="#">Figure 7</a> | 0.5A rated output                                                                                                                       | TPS20xxC                       | 0.67 | 0.85 | 1.01 | A   |      |
|                                                                               | 1 A rated output                                                                                                                        | TPS20xxC                       | 1.3  | 1.55 | 1.8  |     |      |
|                                                                               |                                                                                                                                         | TPS20xxC-2                     | 1.18 | 1.53 | 1.88 |     |      |
|                                                                               | 1.5 A rated output                                                                                                                      | TPS20xxC                       | 1.7  | 2.15 | 2.5  |     |      |
|                                                                               |                                                                                                                                         | TPS20xxC-2                     | 1.71 | 2.23 | 2.75 |     |      |
|                                                                               | 2 A rated output                                                                                                                        | TPS20xxC                       | 2.35 | 2.9  | 3.4  |     |      |
| SUPPLY CURRENT                                                                |                                                                                                                                         |                                |      |      |      |     |      |
| I <sub>SD</sub> Supply current, switch disabled                               | I <sub>OUT</sub> = 0 A                                                                                                                  |                                | 0.01 |      | 1    | μA  |      |
|                                                                               | –40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C, V <sub>IN</sub> = 5.5 V, I <sub>OUT</sub> = 0 A                                      |                                |      |      | 2    |     |      |
| I <sub>SE</sub> Supply current, switch enabled                                | I <sub>OUT</sub> = 0 A                                                                                                                  |                                | 60   |      | 70   | μA  |      |
|                                                                               | –40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C, V <sub>IN</sub> = 5.5 V, I <sub>OUT</sub> = 0 A                                      |                                |      |      | 85   |     |      |
| I <sub>lkg</sub> Leakage current                                              | V <sub>OUT</sub> = 0 V, V <sub>IN</sub> = 5 V, disabled,<br>measure I <sub>VIN</sub>                                                    | TPS20xxC-2                     | 0.05 |      | 1    | μA  |      |
|                                                                               | –40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C, V <sub>OUT</sub> = 0 V,<br>V <sub>IN</sub> = 5 V, disabled, measure I <sub>VIN</sub> |                                |      |      | 2    |     |      |

(1) Pulsed testing techniques maintain junction temperature approximately equal to ambient temperature

(2) See [CURRENT LIMIT](#) section for explanation of this parameter.

# TPS20xxC, TPS20xxC-2

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## ELECTRICAL CHARACTERISTICS: $T_J = T_A = 25^{\circ}\text{C}^{(1)}$ (continued)

Unless otherwise noted:  $V_{IN} = 5\text{ V}$ ,  $V_{EN} = V_{IN}$  or  $\overline{V_{EN}} = \text{GND}$ ,  $I_{OUT} = 0\text{ A}$ . See the 'Device Information' table for the rated current of each part number. Parametrics over a wider operational range are shown in the second 'Electrical Characteristics' table.

| PARAMETER        |                                            | TEST CONDITIONS <sup>(1)</sup>                                                                                              |          | MIN | TYP | MAX | UNIT |
|------------------|--------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------|----------|-----|-----|-----|------|
| I <sub>REV</sub> | Reverse leakage current                    | V <sub>OUT</sub> = 5 V, V <sub>IN</sub> = 0 V, measure I <sub>VOUT</sub>                                                    |          |     | 0.1 | 1   | μA   |
|                  |                                            | −40°C ≤ (T <sub>J</sub> , T <sub>A</sub> ) ≤ 85°C, V <sub>OUT</sub> = 5 V, V <sub>IN</sub> = 0 V, measure I <sub>VOUT</sub> |          |     |     | 5   |      |
| OUTPUT DISCHARGE |                                            |                                                                                                                             |          |     |     |     |      |
| R <sub>PD</sub>  | Output pull-down resistance <sup>(3)</sup> | V <sub>IN</sub> = V <sub>OUT</sub> = 5 V, disabled                                                                          | TPS20xxC | 400 | 470 | 600 | Ω    |

(3) These parameters are provided for reference only, and do not constitute part of TI's published device specifications for purposes of TI's product warranty.

## ELECTRICAL CHARACTERISTICS: $-40^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$

Unless otherwise noted:  $4.5\text{ V} \leq V_{IN} \leq 5.5\text{ V}$ ,  $V_{EN} = V_{IN}$  or  $\overline{V_{EN}} = \text{GND}$ ,  $I_{OUT} = 0\text{ A}$ , typical values are at  $5\text{ V}$  and  $25^{\circ}\text{C}$ . See the DEVICE INFORMATION table for the rated current of each part number.

| PARAMETER                                    |                                                 | TEST CONDITIONS <sup>(1)</sup>                                                                                                                                                                    |            | MIN  | TYP  | MAX  | UNIT |
|----------------------------------------------|-------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|------|------|------|------|
| POWER SWITCH                                 |                                                 |                                                                                                                                                                                                   |            |      |      |      |      |
| R <sub>DS(ON)</sub>                          | Input – output resistance                       | 0.5 A rated output                                                                                                                                                                                | DBV        |      | 97   | 154  | mΩ   |
|                                              |                                                 | 1 A rated output                                                                                                                                                                                  | DBV        |      | 96   | 154  | mΩ   |
|                                              |                                                 |                                                                                                                                                                                                   | DGN        |      | 86   | 140  |      |
|                                              |                                                 | 1.5 A rated output                                                                                                                                                                                | DBV        |      | 76   | 121  | mΩ   |
|                                              |                                                 |                                                                                                                                                                                                   | DGN        |      | 69   | 112  | mΩ   |
|                                              |                                                 | 2 A rated output                                                                                                                                                                                  | DGN, DGK   |      | 72   | 112  | mΩ   |
| ENABLE INPUT (EN or $\overline{\text{EN}}$ ) |                                                 |                                                                                                                                                                                                   |            |      |      |      |      |
|                                              | Threshold                                       | Input rising                                                                                                                                                                                      |            | 1    | 1.45 | 2    | V    |
|                                              | Hysteresis                                      |                                                                                                                                                                                                   |            | 0.07 | 0.13 | 0.20 | V    |
|                                              | Leakage current                                 | (V <sub>EN</sub> or $\overline{\text{V}}_{\text{EN}}$ ) = 0 V or 5.5 V                                                                                                                            |            | –1   | 0    | 1    | μA   |
| t <sub>ON</sub>                              | Turnon time                                     | V <sub>IN</sub> = 5 V, C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, EN ↑ or $\overline{\text{EN}}$ ↓.<br>See <a href="#">Figure 2</a> , <a href="#">Figure 4</a> , and <a href="#">Figure 5</a> |            |      |      |      | ms   |
|                                              |                                                 | 0.5A / 1A Rated                                                                                                                                                                                   |            | 1    | 1.4  | 1.8  |      |
|                                              |                                                 | 1.5A / 2A Rated                                                                                                                                                                                   |            | 1.2  | 1.7  | 2.2  |      |
| t <sub>OFF</sub>                             | Turnoff time                                    | V <sub>IN</sub> = 5 V, C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, EN ↓ or $\overline{\text{EN}}$ ↑.<br>See <a href="#">Figure 2</a> , <a href="#">Figure 4</a> , and <a href="#">Figure 5</a> |            |      |      |      | ms   |
|                                              |                                                 | 0.5A and 1A Rated                                                                                                                                                                                 |            | 1.3  | 1.65 | 2    |      |
|                                              |                                                 | 1.5A / 2A Rated                                                                                                                                                                                   |            | 1.7  | 2.1  | 2.5  |      |
| t <sub>R</sub>                               | Rise time, output                               | C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, V <sub>IN</sub> = 5 V. See <a href="#">Figure 3</a>                                                                                                |            |      |      |      | ms   |
|                                              |                                                 | 0.5A / 1A Rated                                                                                                                                                                                   |            | 0.4  | 0.55 | 0.7  |      |
|                                              |                                                 | 1.5A / 2A Rated                                                                                                                                                                                   |            | 0.5  | 0.7  | 1.0  |      |
| t <sub>F</sub>                               | Fall time, output                               | C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, V <sub>IN</sub> = 5 V. See <a href="#">Figure 3</a>                                                                                                |            |      |      |      | ms   |
|                                              |                                                 | 0.5A / 1A Rated                                                                                                                                                                                   |            | 0.25 | 0.35 | 0.45 |      |
|                                              |                                                 | 1.5A / 2A Rated                                                                                                                                                                                   |            | 0.3  | 0.43 | 0.55 |      |
| CURRENT LIMIT                                |                                                 |                                                                                                                                                                                                   |            |      |      |      |      |
| I <sub>OS</sub> <sup>(2)</sup>               | Current-limit,<br>See <a href="#">Figure 10</a> | 0.5 A rated output                                                                                                                                                                                | TPS20xxC   | 0.65 | 0.85 | 1.05 | A    |
|                                              |                                                 | 1 A rated output                                                                                                                                                                                  | TPS20xxC   | 1.2  | 1.55 | 1.9  |      |
|                                              |                                                 |                                                                                                                                                                                                   | TPS20xxC-2 | 1.1  | 1.53 | 1.96 |      |
|                                              |                                                 | 1.5 A rated output                                                                                                                                                                                | TPS20xxC   | 1.6  | 2.15 | 2.7  |      |
|                                              |                                                 |                                                                                                                                                                                                   | TPS20xxC-2 | 1.6  | 2.23 | 2.86 |      |
|                                              |                                                 | 2 A rated output                                                                                                                                                                                  | TPS20xxC   | 2.3  | 2.9  | 3.6  |      |

(1) Pulsed testing techniques maintain junction temperature approximately equal to ambient temperature

(2) See [CURRENT LIMIT](#) section for explanation of this parameter.

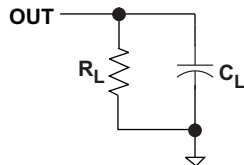
**ELECTRICAL CHARACTERISTICS:  $-40^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$  (continued)**

Unless otherwise noted:  $4.5\text{ V} \leq V_{\text{IN}} \leq 5.5\text{ V}$ ,  $V_{\text{EN}} = V_{\text{IN}}$  or  $V_{\text{EN}} = \text{GND}$ ,  $I_{\text{OUT}} = 0\text{ A}$ , typical values are at  $5\text{ V}$  and  $25^{\circ}\text{C}$ . See the DEVICE INFORMATION table for the rated current of each part number.

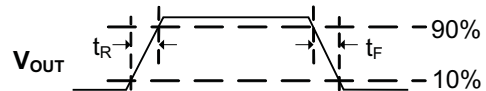
| PARAMETER                                                   | TEST CONDITIONS <sup>(1)</sup>                                                                                                                                                                      | MIN      | TYP  | MAX | UNIT               |
|-------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------|------|-----|--------------------|
| $t_{\text{IOS}}$ Short-circuit response time <sup>(3)</sup> | $V_{\text{IN}} = 5\text{ V}$ (see Figure 7),<br>One-half full load $\rightarrow R_{\text{SHORT}} = 50\text{ m}\Omega$ ,<br>Measure from application to when current falls below 120% of final value |          | 2    |     | $\mu\text{s}$      |
| <b>SUPPLY CURRENT</b>                                       |                                                                                                                                                                                                     |          |      |     |                    |
| $I_{\text{SD}}$ Supply current, switch disabled             | $I_{\text{OUT}} = 0\text{ A}$                                                                                                                                                                       |          | 0.01 | 10  | $\mu\text{A}$      |
| $I_{\text{SE}}$ Supply current, switch enabled              | $I_{\text{OUT}} = 0\text{ A}$                                                                                                                                                                       |          | 65   | 90  | $\mu\text{A}$      |
| $I_{\text{IKG}}$ Leakage current                            | $V_{\text{OUT}} = 0\text{ V}$ , $V_{\text{IN}} = 5\text{ V}$ , disabled, measure $I_{\text{VIN}}$ TPS20XXC-2                                                                                        |          | 0.05 |     | $\mu\text{A}$      |
| $I_{\text{REV}}$ Reverse leakage current                    | $V_{\text{OUT}} = 5.5\text{ V}$ , $V_{\text{IN}} = 0\text{ V}$ , measure $I_{\text{VOUT}}$                                                                                                          |          | 0.2  | 20  | $\mu\text{A}$      |
| <b>UNDERVOLTAGE LOCKOUT</b>                                 |                                                                                                                                                                                                     |          |      |     |                    |
| $V_{\text{UVLO}}$ Rising threshold                          | $V_{\text{IN}} \uparrow$                                                                                                                                                                            | 3.5      | 3.75 | 4   | V                  |
| Hysteresis <sup>(3)</sup>                                   | $V_{\text{IN}} \downarrow$                                                                                                                                                                          |          | 0.14 |     | V                  |
| <b>FLT</b>                                                  |                                                                                                                                                                                                     |          |      |     |                    |
| Output low voltage, $\overline{\text{FLT}}$                 | $I_{\text{FLT}} = 1\text{ mA}$                                                                                                                                                                      |          |      | 0.2 | V                  |
| Off-state leakage                                           | $V_{\text{FLT}} = 5.5\text{ V}$                                                                                                                                                                     |          |      | 1   | $\mu\text{A}$      |
| $t_{\text{FLT}}$ $\overline{\text{FLT}}$ deglitch           | $\overline{\text{FLT}}$ assertion or deassertion deglitch                                                                                                                                           | 6        | 9    | 12  | ms                 |
| <b>OUTPUT DISCHARGE</b>                                     |                                                                                                                                                                                                     |          |      |     |                    |
| $R_{\text{PD}}$ Output pull-down resistance                 | $V_{\text{IN}} = 4\text{ V}$ , $V_{\text{OUT}} = 5\text{ V}$ , disabled                                                                                                                             | TPS20XXC | 350  | 560 | 1200               |
|                                                             | $V_{\text{IN}} = 5\text{ V}$ , $V_{\text{OUT}} = 5\text{ V}$ , disabled                                                                                                                             | TPS20XXC | 300  | 470 | 800                |
| <b>THERMAL SHUTDOWN</b>                                     |                                                                                                                                                                                                     |          |      |     |                    |
| Rising threshold ( $T_J$ )                                  | In current limit                                                                                                                                                                                    |          | 135  |     | $^{\circ}\text{C}$ |
|                                                             | Not in current limit                                                                                                                                                                                |          | 155  |     |                    |
| Hysteresis <sup>(4)</sup>                                   |                                                                                                                                                                                                     |          | 20   |     |                    |

(3) These parameters are provided for reference only, and do not constitute part of TI's published device specifications for purposes of TI's product warranty.

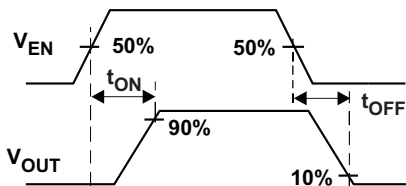
(4) These parameters are provided for reference only, and do not constitute part of TI's published device specifications for purposes of TI's product warranty.



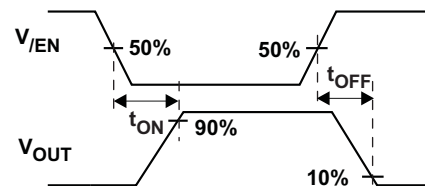
**Figure 2. Output Rise / Fall Test Load**



**Figure 3. Power-On and Off Timing**



**Figure 4. Enable Timing, Active High Enable**

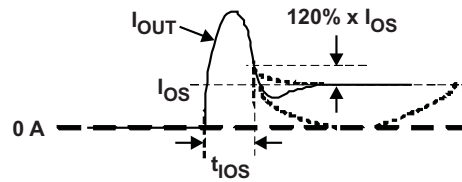


**Figure 5. Enable Timing, Active Low Enable**

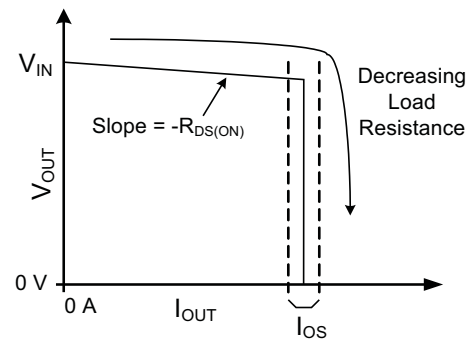
# TPS20xxC, TPS20xxC-2

SLVSAU6F–JUNE 2011–REVISED NOVEMBER 2012

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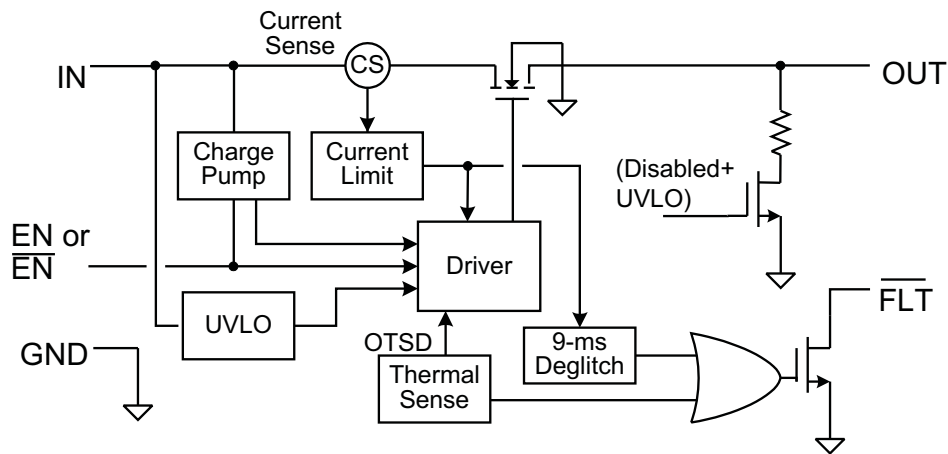


**Figure 6. Output Short Circuit Parameters**

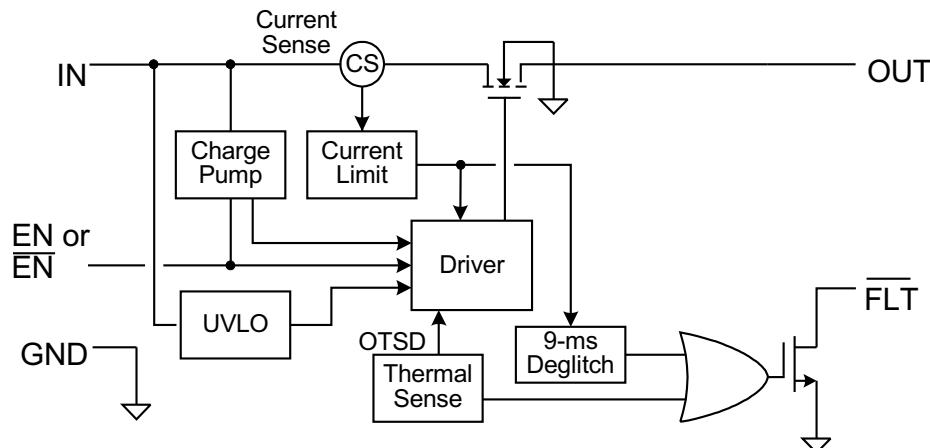


**Figure 7. Output Characteristic Showing Current Limit**

## FUNCTIONAL BLOCK DIAGRAM



**Figure 8. TPS20xxC Block Diagram**



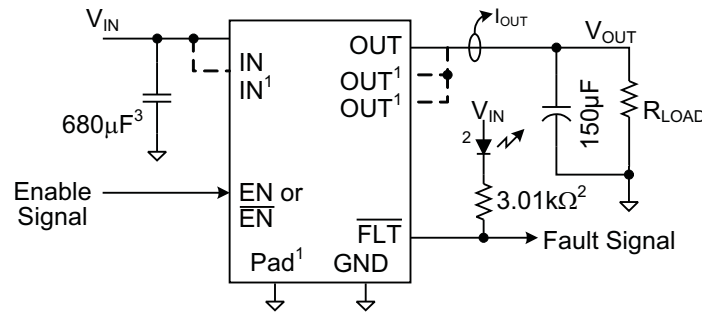
**Figure 9. TPS20xxC-2 Block Diagram**

## DEVICE INFORMATION

### PIN FUNCTIONS

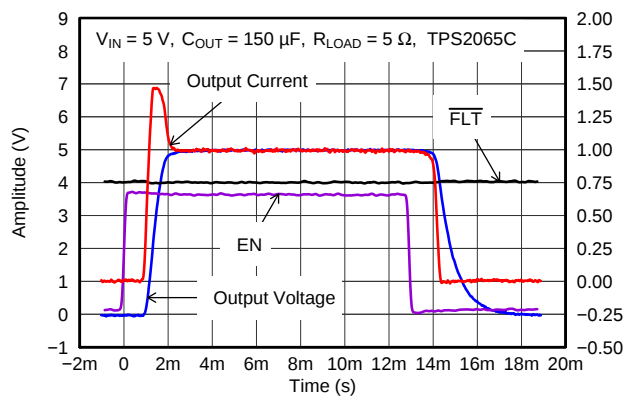
| NAME                         | PINS    | DESCRIPTION                                                                                                                                                                                                                     |
|------------------------------|---------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>8-PIN PACKAGE</b>         |         |                                                                                                                                                                                                                                 |
| EN or $\overline{\text{EN}}$ | 4       | Enable input, logic high turns on power switch                                                                                                                                                                                  |
| GND                          | 1       | Ground connection                                                                                                                                                                                                               |
| IN                           | 2, 3    | Input voltage and power-switch drain; connect a 0.1 $\mu\text{F}$ or greater ceramic capacitor from IN to GND close to the IC                                                                                                   |
| $\overline{\text{FLT}}$      | 5       | Active-low open-drain output, asserted during over-current, or over-temperature conditions                                                                                                                                      |
| OUT                          | 6, 7, 8 | Power-switch output, connect to load                                                                                                                                                                                            |
| PowerPAD (DGN ONLY)          | PAD     | Internally connected to GND. Connect PAD to GND plane as a heatsink for the best thermal performance. PAD may be left floating if desired. See <a href="#">POWER DISSIPATION AND JUNCTION TEMPERATURE</a> section for guidance. |
| <b>5-PIN PACKAGE</b>         |         |                                                                                                                                                                                                                                 |
| EN or $\overline{\text{EN}}$ | 4       | Enable input, logic high turns on power switch                                                                                                                                                                                  |
| GND                          | 2       | Ground connection                                                                                                                                                                                                               |
| IN                           | 5       | Input voltage and power-switch drain; connect a 0.1 $\mu\text{F}$ or greater ceramic capacitor from IN to GND close to the IC                                                                                                   |
| $\overline{\text{FLT}}$      | 3       | Active-low open-drain output, asserted during over-current, or over-temperature conditions                                                                                                                                      |
| OUT                          | 1       | Power-switch output, connect to load.                                                                                                                                                                                           |

## TYPICAL CHARACTERISTICS

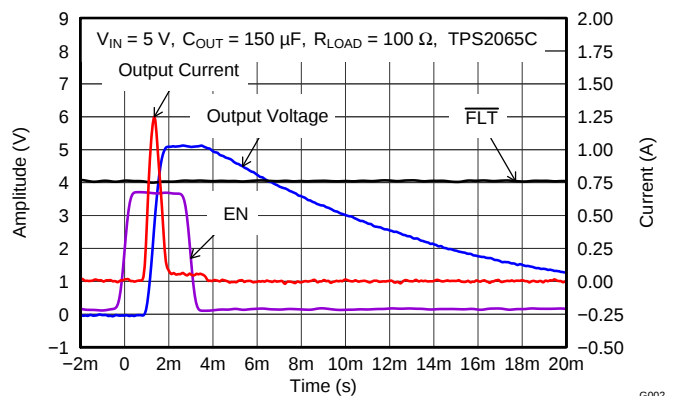


- (1) Not every package has all pins
- (2) These parts are for test purposes
- (3) Helps with output shorting tests when external supply is used.

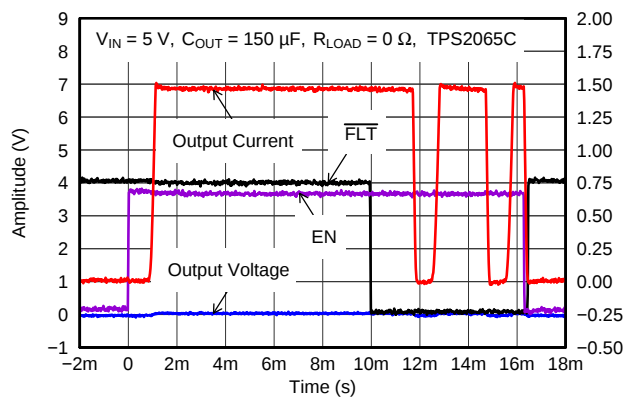
**Figure 10. Test Circuit for System Operation in Typical Characteristics Section**



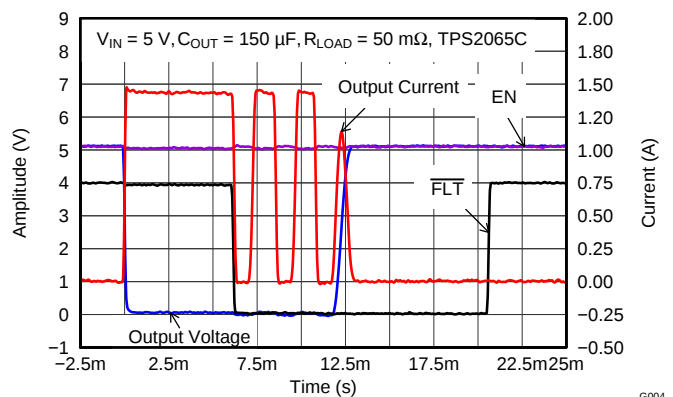
**Figure 11. TPS2065C Output Rise / Fall 5Ω**



**Figure 12. TPS2065C Output Rise / Fall 100Ω**



**Figure 13. TPS2065C Enable into Output Short**



**Figure 14. TPS2065C Pulsed Short Applied**

## TYPICAL CHARACTERISTICS (continued)

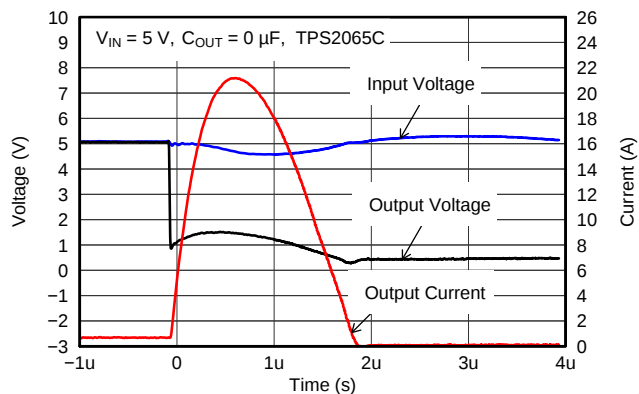


Figure 15. TPS2065C Short Applied

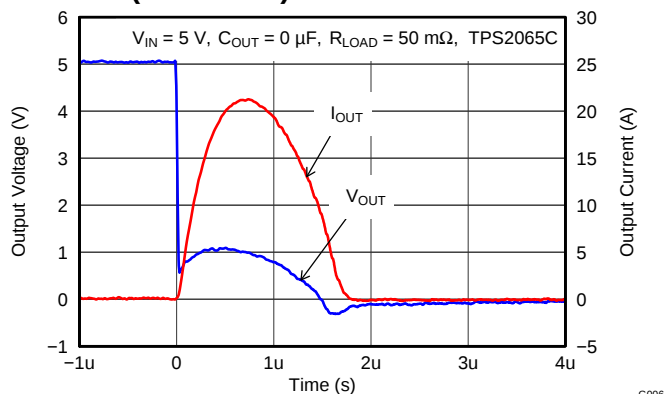


Figure 16. TPS2065C Pulsed 1.45-A Load

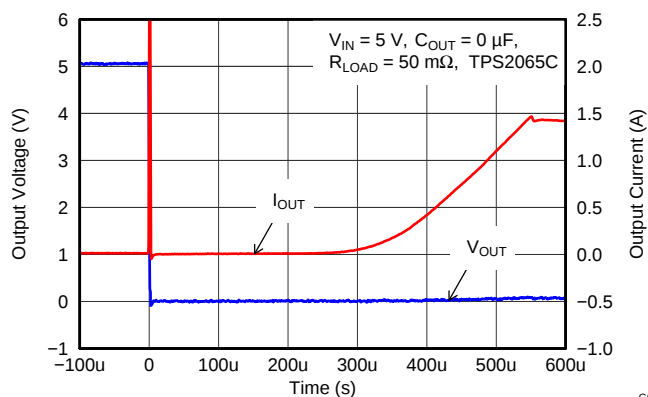


Figure 17. TPS2065C 50 m $\Omega$  Short Circuit

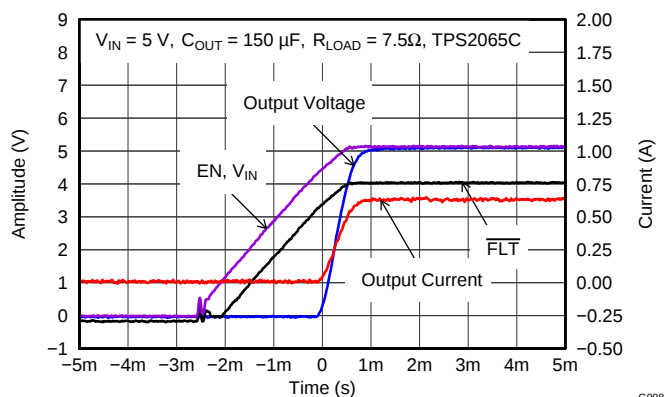


Figure 18. TPS2065C Power Up - Enabled

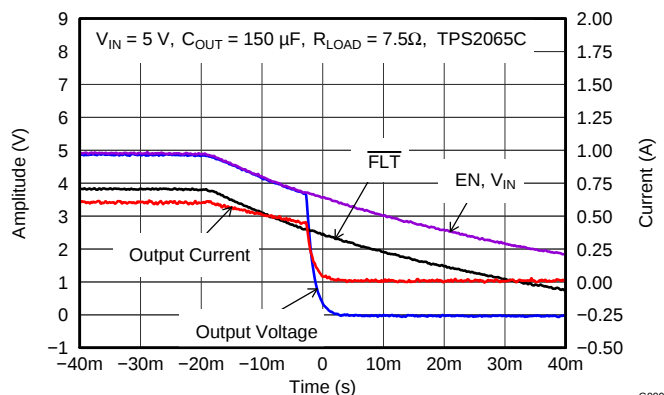


Figure 19. TPS2065C Power Down - Enabled

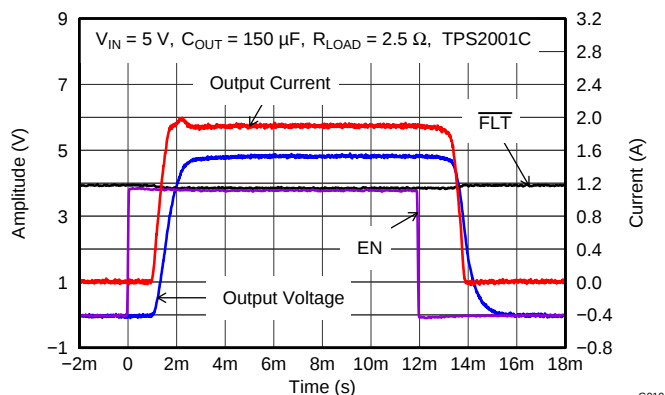
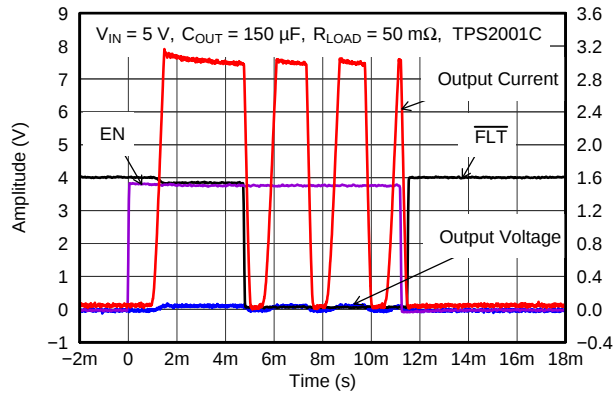
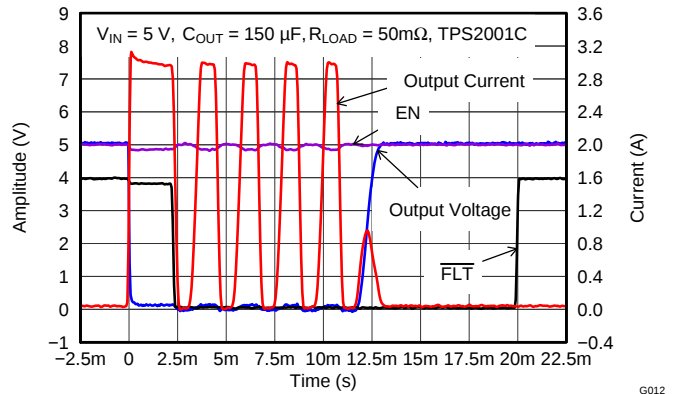


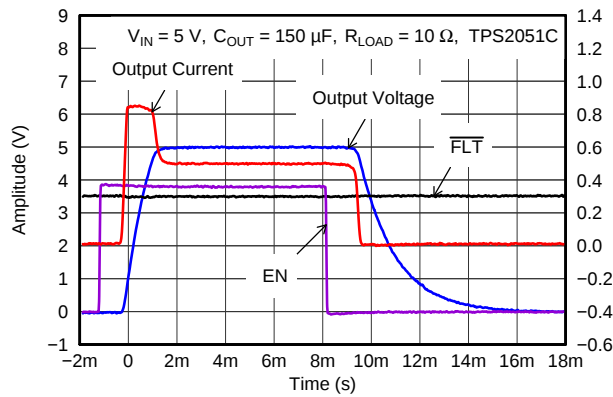
Figure 20. TPS2001C Turn ON into 2.5 $\Omega$

**TYPICAL CHARACTERISTICS (continued)**

**Figure 21. TPS2001C Enable into Short**

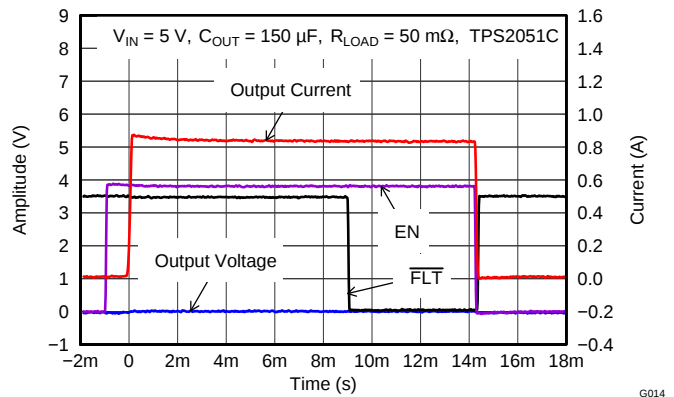
G011


**Figure 22. TPS2001C Pulsed Output Short**

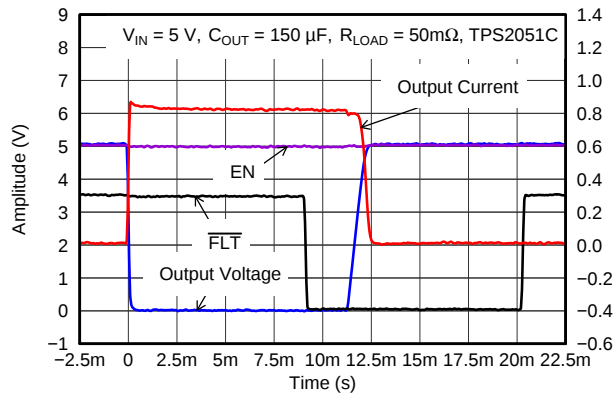
G012


**Figure 23. TPS2051C Turn ON into 10Ω**

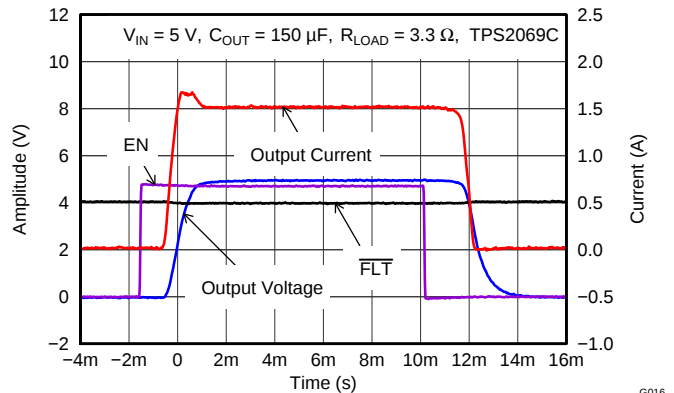
G013


**Figure 24. TPS2051C Enable into Short**

G014

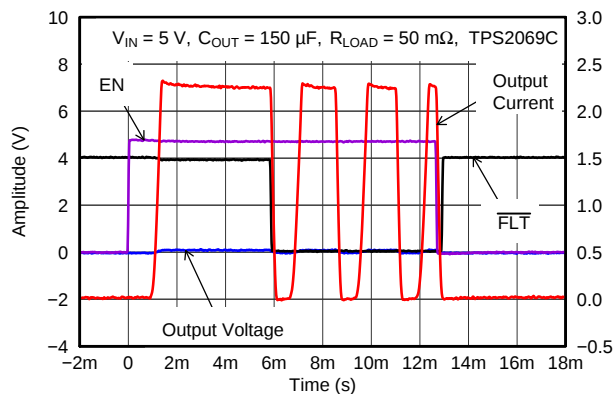

**Figure 25. TPS2051C Pulsed Output Short**

G015

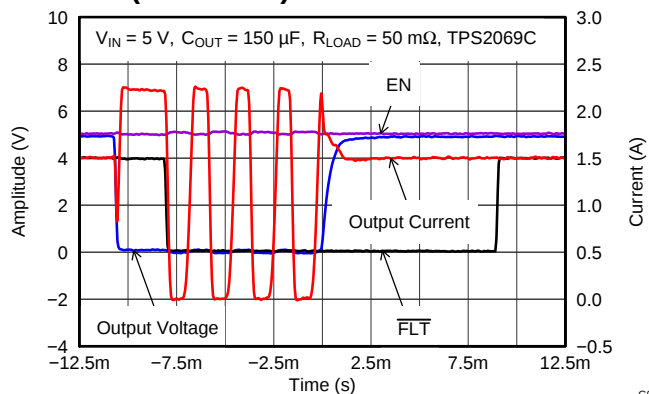

**Figure 26. TPS2069C Turn ON into 3.3Ω**

G016

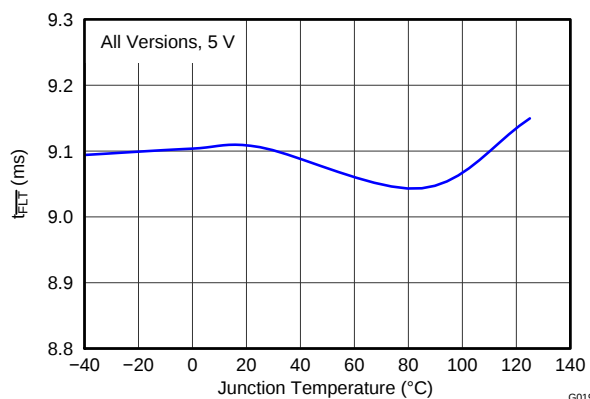
# TYPICAL CHARACTERISTICS (continued)



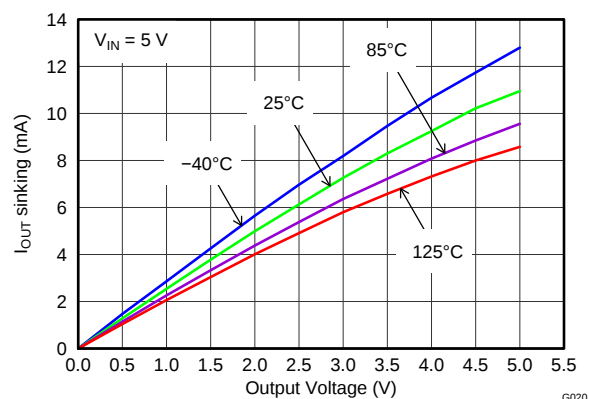
**Figure 27. TPS2069C Enable into Short**



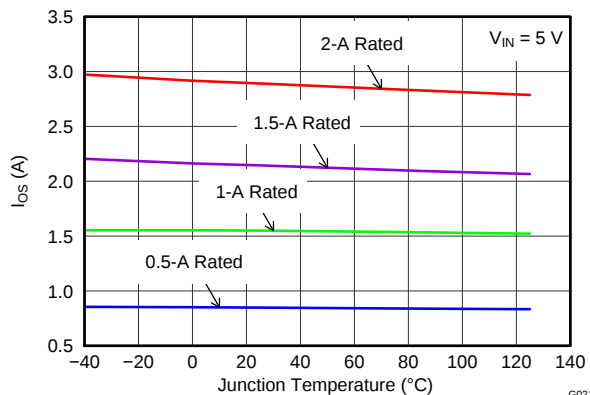
**Figure 28. TPS2069C Pulsed Output Short**



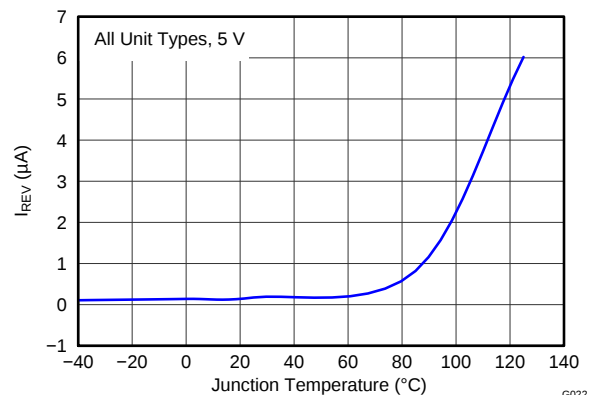
**Figure 29. Deglitch Period ( $t_{FLT}$ ) vs Temperature**



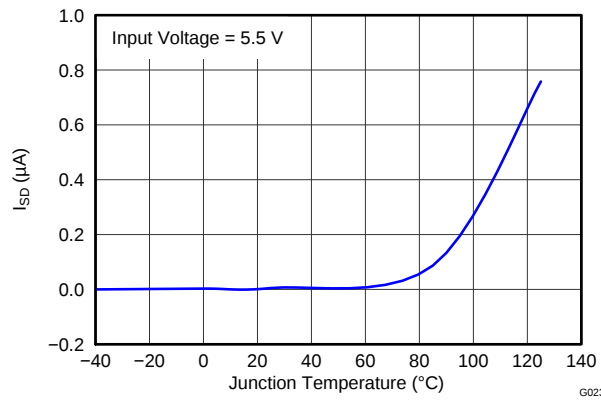
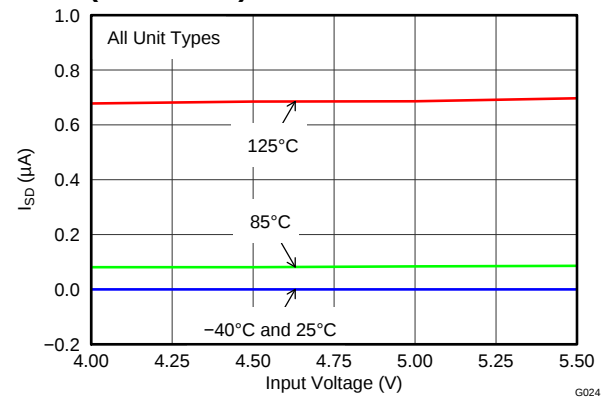
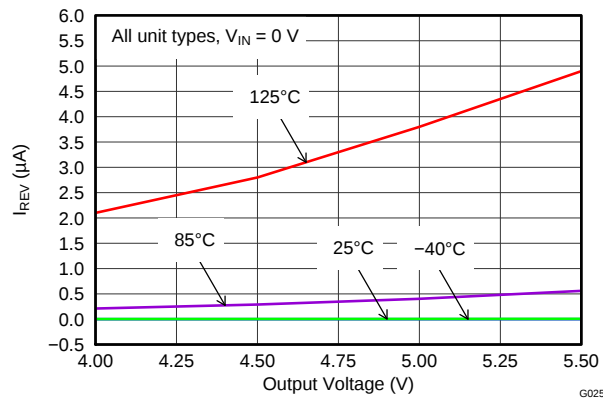
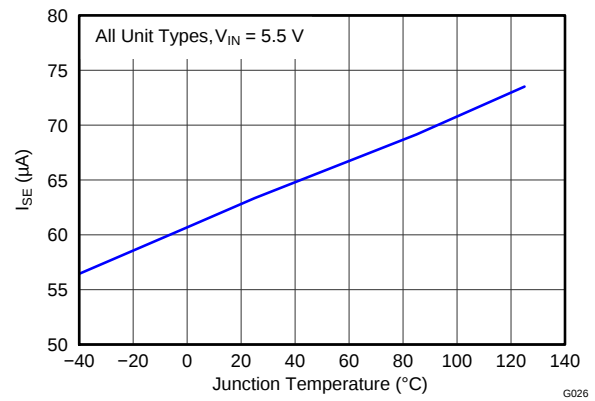
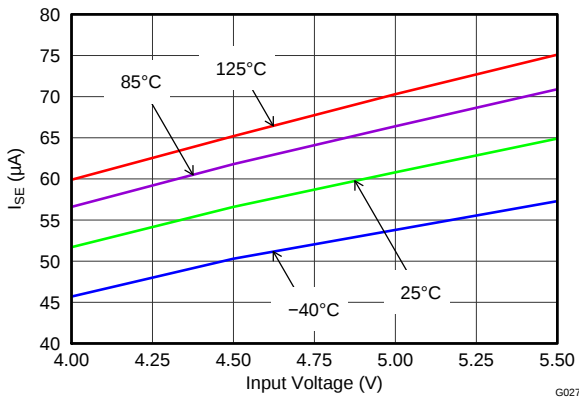
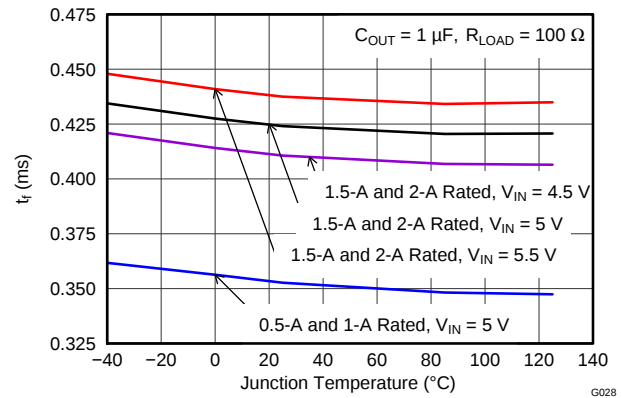
**Figure 30. Output Discharge Current vs Output Voltage**



**Figure 31. Short Circuit Current ( $I_{OS}$ ) vs Temperature**



**Figure 32. Reverse Leakage Current ( $I_{REV}$ ) vs Temperature**

**TYPICAL CHARACTERISTICS (continued)**

**Figure 33. Disabled Supply Current ( $I_{SD}$ ) vs Temperature**

**Figure 34. Disabled Supply Current ( $I_{SD}$ ) vs Input Voltage**

**Figure 35. Reverse Leakage Current ( $I_{REV}$ ) vs Output Voltage**

**Figure 36. Enabled Supply Current ( $I_{SE}$ ) vs Temperature**

**Figure 37. Enabled Supply Current ( $I_{SE}$ ) vs Input Voltage**

**Figure 38. Output Fall Time ( $t_F$ ) vs Temperature**

### TYPICAL CHARACTERISTICS (continued)

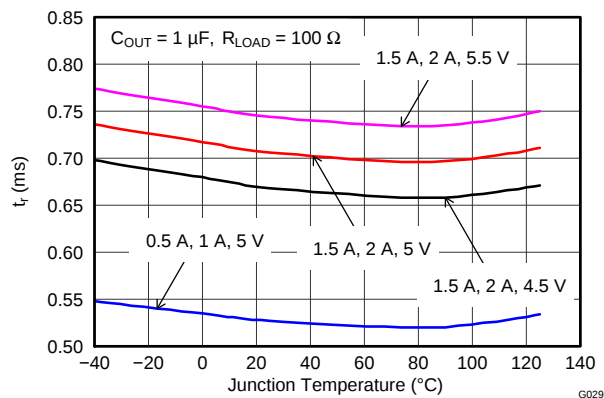


Figure 39. Output Rise Time ( $t_R$ ) vs Temperature

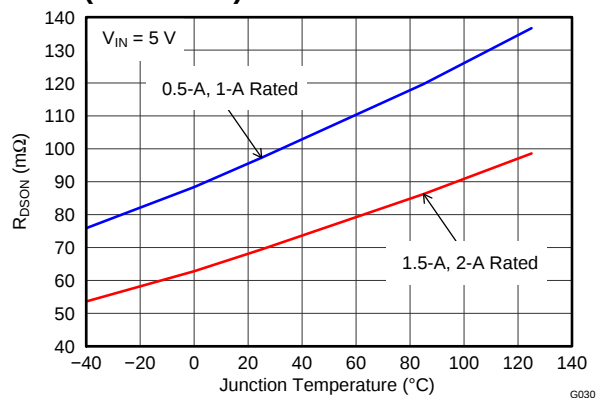


Figure 40. Input-Output Resistance ( $R_{DS(ON)}$ ) vs Temperature

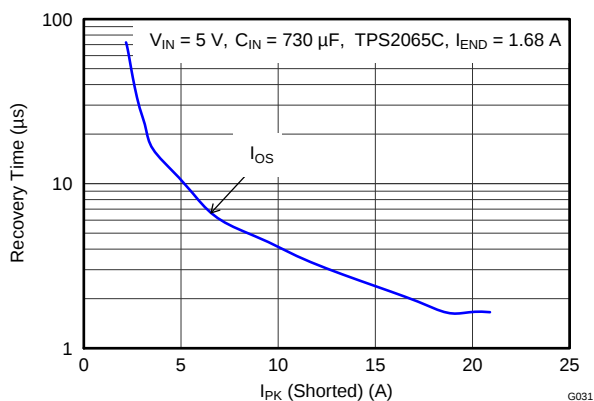


Figure 41. Recovery vs Current Peak

## DETAILED DESCRIPTION

The TPS20xxC and TPS20xxC-2 are current-limited, power-distribution switches providing between 0.5 A and 2 A of continuous load current in 5 V circuits. These parts use N-channel MOSFETs for low resistance, maintaining voltage regulation to the load. They are designed for applications where short circuits or heavy capacitive loads will be encountered. Device features include enable, reverse blocking when disabled, output discharge pulldown, overcurrent protection, over-temperature protection, and deglitched fault reporting.

### UVLO

The undervoltage lockout (UVLO) circuit disables the power switch until the input voltage reaches the UVLO turn-on threshold. Built-in hysteresis prevents unwanted on/off cycling due to input voltage drop from large current surges. FLT is high impedance when the TPS20xxC and TPS20xxC-2 are in UVLO.

### ENABLE

The logic enable input (EN, or  $\overline{\text{EN}}$ ), controls the power switch, bias for the charge pump, driver, and other circuits. The supply current is reduced to less than 1  $\mu\text{A}$  when the TPS20xxC and TPS20xxC-2 are disabled. Disabling the TPS20xxC and TPS20xxC-2 will immediately clear an active  $\overline{\text{FLT}}$  indication. The enable input is compatible with both TTL and CMOS logic levels.

The turnon and turnoff times ( $t_{\text{ON}}$ ,  $t_{\text{OFF}}$ ) are composed of a delay and a rise or fall time ( $t_{\text{R}}$ ,  $t_{\text{F}}$ ). The delay times are internally controlled. The rise time is controlled by both the TPS20xxC and TPS20xxC-2 and the external loading (especially capacitance). TPS20xxC fall time is controlled by the loading (R and C), and the output discharge ( $R_{\text{PD}}$ ). TPS20xxC-2 does not have the output discharge ( $R_{\text{PD}}$ ), fall time is controlled by the loading (R and C). An output load consisting of only a resistor will experience a fall time set by the TPS20xxC and TPS20xxC-2. An output load with parallel R and C elements will experience a fall time determined by the (R  $\times$  C) time constant if it is longer than the TPS20xxC and TPS20xxC-2's  $t_{\text{F}}$ .

The enable should not be left open, and may be tied to VIN or GND depending on the device.

### INTERNAL CHARGE PUMP

The device incorporates an internal charge pump and gate drive circuitry necessary to drive the N-channel MOSFET. The charge pump supplies power to the gate driver circuit and provides the necessary voltage to pull the gate of the MOSFET above the source. The driver incorporates circuitry that controls the rise and fall times of the output voltage to limit large current and voltage surges on the input supply, and provides built-in soft-start functionality. The MOSFET power switch will block current from OUT to IN when turned off by the UVLO or disabled.

### CURRENT LIMIT

The TPS20xxC and TPS20xxC-2 responds to overloads by limiting output current to the static  $I_{\text{OS}}$  levels shown in the Electrical Characteristics table. When an overload condition is present, the device maintains a constant output current, with the output voltage determined by ( $I_{\text{OS}} \times R_{\text{LOAD}}$ ). Two possible overload conditions can occur.

The first overload condition occurs when either: 1) input voltage is first applied, enable is true, and a short circuit is present (load which draws  $I_{\text{OUT}} > I_{\text{OS}}$ ), or 2) input voltage is present and the TPS20xxC and TPS20xxC-2 are enabled into a short circuit. The output voltage is held near zero potential with respect to ground and the TPS20xxC and TPS20xxC-2 ramps the output current to  $I_{\text{OS}}$ . The TPS20xxC and TPS20xxC-2 will limit the current to  $I_{\text{OS}}$  until the overload condition is removed or the device begins to thermal cycle. This is demonstrated in [Figure 13](#) where the device was enabled into a short, and subsequently cycles current off and on as the thermal protection engages.

The second condition is when an overload occurs while the device is enabled and fully turned on. The device responds to the overload condition within  $t_{\text{IOS}}$  ([Figure 6](#) and [Figure 7](#)) when the specified overload (per Electrical Characteristics table) is applied. The response speed and shape will vary with the overload level, input circuit, and rate of application. The current-limit response will vary between simply settling to  $I_{\text{OS}}$ , or turnoff and controlled return to  $I_{\text{OS}}$ . Similar to the previous case, the TPS20xxC and TPS20xxC-2 will limit the current to  $I_{\text{OS}}$  until the overload condition is removed or the device begins to thermal cycle. This is demonstrated by [Figure 14](#), [Figure 15](#), and [Figure 16](#).

The TPS20xxC and TPS20xxC-2 thermal cycles if an overload condition is present long enough to activate thermal limiting in any of the above cases. This is due to the relatively large power dissipation  $[(V_{IN} - V_{OUT}) \times I_{OS}]$  driving the junction temperature up. The device turns off when the junction temperature exceeds 135°C (min) while in current limit. The device remains off until the junction temperature cools 20°C and then restarts.

There are two kinds of current limit profiles typically available in TI switch products similar to the TPS20xxC and TPS20xxC-2. Many older designs have an output  $I$  vs  $V$  characteristic similar to the plot labeled "Current Limit with Peaking" in Figure 42. This type of limiting can be characterized by two parameters, the current limit corner ( $I_{OC}$ ), and the short circuit current ( $I_{OS}$ ).  $I_{OC}$  is often specified as a maximum value. The TPS20xxC and TPS20xxC-2 family of parts does not present noticeable peaking in the current limit, corresponding to the characteristic labeled "Flat Current Limit" in Figure 42. This is why the  $I_{OC}$  parameter is not present in the Electrical Characteristics tables.

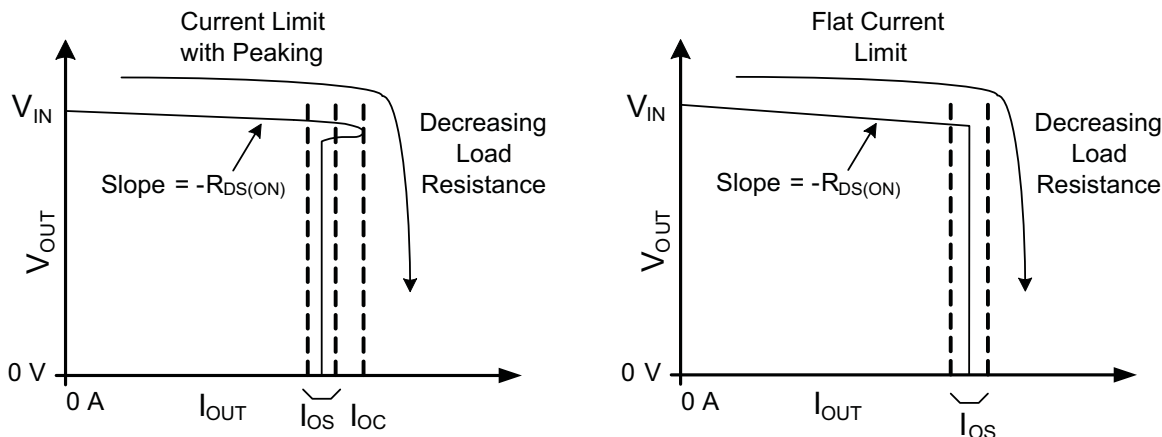


Figure 42. Current Limit Profiles

## FLT

The  $\overline{FLT}$  open-drain output is asserted (active low) during an overload or over-temperature condition. A 9 ms deglitch on both the rising and falling edges avoids false reporting at startup and during transients. A current limit condition shorter than the deglitch period will clear the internal timer upon termination. The deglitch timer will not integrate multiple short overloads and declare a fault. This is also true for exiting from a faulted state. An input voltage with excessive ripple and large output capacitance may interfere with operation of  $\overline{FLT}$  around  $I_{OS}$  as the ripple will drive the TPS20xxC and TPS20xxC-2 in and out of current limit.

If the TPS20xxC and TPS20xxC-2 are in current limit and the over-temperature circuit goes active,  $\overline{FLT}$  will go true immediately (see Figure 14) however exiting this condition is deglitched (see Figure 16).  $\overline{FLT}$  is tripped just as the knee of the constant-current limiting is entered. Disabling the TPS20xxC and TPS20xxC-2 will clear an active  $\overline{FLT}$  as soon as the switch turns off (see Figure 13).  $\overline{FLT}$  is high impedance when the TPS20xxC and TPS20xxC-2 are disabled or in under-voltage lockout (UVLO).

## OUTPUT DISCHARGE

A 470Ω (typical) output discharge will dissipate stored charge and leakage current on OUT when the TPS20xxC is in UVLO or disabled. The pull-down circuit will lose bias gradually as  $V_{IN}$  decreases, causing a rise in the discharge resistance as  $V_{IN}$  falls towards 0 V. The TPS20xxC-2 does not have this function. The output is be controlled by an external loadings when the device is in ULVO or disabled.

## APPLICATION INFORMATION

### INPUT AND OUTPUT CAPACITANCE

Input and output capacitance improves the performance of the device; the actual capacitance should be optimized for the particular application. For all applications, a 0.1  $\mu\text{F}$  or greater ceramic bypass capacitor between IN and GND is recommended as close to the device as possible for local noise decoupling.

All protection circuits such as the TPS20xxC and TPS20xxC-2 will have the potential for input voltage overshoots and output voltage undershoots.

Input voltage overshoots can be caused by either of two effects. The first cause is an abrupt application of input voltage in conjunction with input power bus inductance and input capacitance when the IN terminal is high impedance (before turn on). Theoretically, the peak voltage is 2 times the applied. The second cause is due to the abrupt reduction of output short circuit current when the TPS20xxC and TPS20xxC-2 turns off and energy stored in the input inductance drives the input voltage high. Input voltage droops may also occur with large load steps and as the TPS20xxC and TPS20xxC-2 output is shorted. Applications with large input inductance (e.g. connecting the evaluation board to the bench power-supply through long cables) may require large input capacitance reduce the voltage overshoot from exceeding the absolute maximum voltage of the device. The fast current-limit speed of the TPS20xxC and TPS20xxC-2 to hard output short circuits isolates the input bus from faults. However, ceramic input capacitance in the range of 1 $\mu\text{F}$  to 22 $\mu\text{F}$  adjacent to the TPS20xxC and TPS20xxC-2 input aids in both speeding the response time and limiting the transient seen on the input power bus. Momentary input transients to 6.5V are permitted.

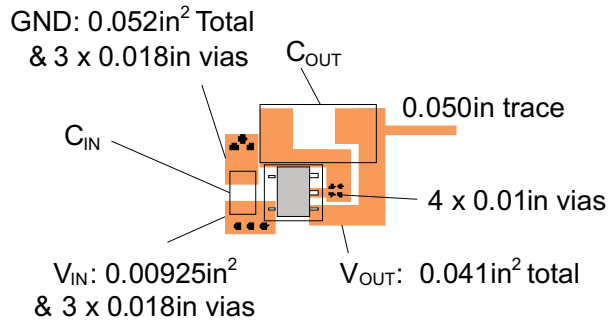
Output voltage undershoot is caused by the inductance of the output power bus just after a short has occurred and the TPS20xxC and TPS20xxC-2 has abruptly reduced OUT current. Energy stored in the inductance will drive the OUT voltage down and potentially negative as it discharges. Applications with large output inductance (such as from a cable) benefit from use of a high-value output capacitor to control the voltage undershoot. When implementing USB standard applications, a 120  $\mu\text{F}$  minimum output capacitance is required. Typically a 150  $\mu\text{F}$  electrolytic capacitor is used, which is sufficient to control voltage undershoots. However, if the application does not require 120  $\mu\text{F}$  of capacitance, and there is potential to drive the output negative, a minimum of 10  $\mu\text{F}$  ceramic capacitance on the output is recommended. The voltage undershoot should be controlled to less than 1.5 V for 10  $\mu\text{s}$ .

### POWER DISSIPATION AND JUNCTION TEMPERATURE

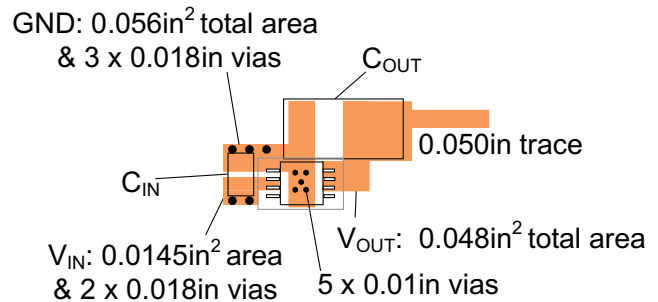
It is good design practice to estimate power dissipation and maximum expected junction temperature of the TPS20xxC and TPS20xxC-2. The system designer can control choices of package, proximity to other power dissipating devices, and printed circuit board (PCB) design based on these calculations. These have a direct influence on maximum junction temperature. Other factors, such as airflow and maximum ambient temperature, are often determined by system considerations. It is important to remember that these calculations do not include the effects of adjacent heat sources, and enhanced or restricted air flow.

Addition of extra PCB copper area around these devices is recommended to reduce the thermal impedance and maintain the junction temperature as low as practical. The lower junction temperatures achieved by soldering the pad improve the efficiency and reliability of both TPS20xxC and TPS20xxC-2 parts and the system. The following examples were used to determine the  $\theta_{JA}$ . Custom thermal impedances noted in the THERMAL INFORMATION table. They were based on use of the JEDEC high-k circuit board construction (2 signal and 2 plane) with 4, 1oz. copper weight, layers.

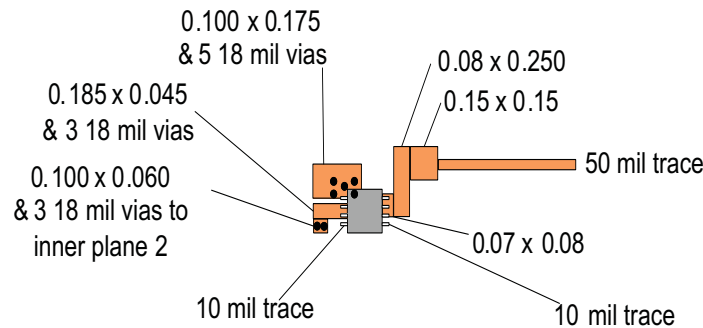
While it is recommended that the DGN package PAD be soldered to circuit board copper fill and vias for low thermal impedance, there may be cases where this is not desired. For example, use of routing area under the IC. Some devices are available in packages without the Power Pad (DGK) specifically for this purpose. The  $\theta_{JA}$  for the DGN package with the pad not soldered and no extra copper, is approximately 141°C/W for 0.5 - A and 1- A rated parts, and 139°C/W for the 1.5 - A and 2- A rated parts. The  $\theta_{JA}$  for the DGK mounted per [Figure 45](#) is 110.3°C/W. These values may be used in [Equation 1](#) to determine the maximum junction temperature.



**Figure 43. DBV Package PCB Layout Example**



**Figure 44. DGN Package PCB Layout Example**



**Figure 45. DGK Package PCB Layout Example**

The following procedure requires iteration because power loss is due to the internal MOSFET  $I^2 \times R_{DS(ON)}$ , and  $R_{DS(ON)}$  is a function of the junction temperature. As an initial estimate, use the  $R_{DS(ON)}$  at 125°C from the TYPICAL CHARACTERISTICS, and the preferred package thermal resistance for the preferred board construction from the THERMAL INFORMATION table.

$$T_J = T_A + ((I_{OUT})^2 \times R_{DS(ON)}) \times \theta_{JA} \quad (1)$$

Where:

- $I_{OUT}$  = rated OUT pin current (A)
- $R_{DS(ON)}$  = Power switch on-resistance at an assumed  $T_J$  ( $\Omega$ )
- $T_A$  = Maximum ambient temperature ( $^{\circ}\text{C}$ )
- $T_J$  = Maximum junction temperature ( $^{\circ}\text{C}$ )
- $\theta_{JA}$  = Thermal resistance ( $^{\circ}\text{C}/\text{W}$ )

If the calculated  $T_J$  is substantially different from the original assumption, estimate a new value of  $R_{DS(ON)}$  using the typical characteristic plot and recalculate.

If the resulting  $T_J$  is not less than 125°C, try a PCB construction and/or package with lower  $\theta_{JA}$ .

## REVISION HISTORY

| Changes from Original (June 2011) to Revision A                                                                                                                                                                                                                                                                                                                                                                                               | Page |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|
| <ul style="list-style-type: none"> <li>Changed the TPS2051C, TPS2065C, and TPS2069C Devices Status From: Preview To: Active ..... 1</li> <li>Corrected pinout numbers for the 5-PIN PACKAGE ..... 7</li> </ul>                                                                                                                                                                                                                                |      |
| Changes from Revision A (July 2011) to Revision B                                                                                                                                                                                                                                                                                                                                                                                             | Page |
| <ul style="list-style-type: none"> <li>Added the DGK Package Information throughout the data sheet ..... 1</li> <li>Changed title of <a href="#">Figure 17</a> From: NEW FIG To: TPS2065C 50 <math>\Omega</math> Short Circuit ..... 9</li> </ul>                                                                                                                                                                                             |      |
| Changes from Revision B (September 2011) to Revision C                                                                                                                                                                                                                                                                                                                                                                                        | Page |
| <ul style="list-style-type: none"> <li>Changed TPS2000C (MSOP-8) status From: Preview To: Active in Table 1 ..... 1</li> <li>Changed From: PXF1 To: PXFI and From: PSG1 To: PXGI in the DEVICE INFORMATION table MOSP-8 (DGK) column ..... 2</li> <li>Changed the <math>\theta_{JA}</math> Custom 2 A Rated DGK value from N/A to 110.3 ..... 2</li> <li>Added <a href="#">Figure 45</a> - DGK Package PCB Layout Example ..... 17</li> </ul> |      |
| Changes from Revision C (October 2011) to Revision D                                                                                                                                                                                                                                                                                                                                                                                          | Page |
| <ul style="list-style-type: none"> <li>Added Feature UL Listed and CB-File No. E169910 (See <a href="#">Table 1</a>) ..... 1</li> <li>Added table Note 2, UL listed and CB complete. .... 1</li> <li>Added <math>V_{IH}</math> and <math>V_{IL}</math> information to the ROC Table ..... 3</li> </ul>                                                                                                                                        |      |
| Changes from Revision D (February 2012) to Revision E                                                                                                                                                                                                                                                                                                                                                                                         | Page |
| <ul style="list-style-type: none"> <li>Changed the POWER DISSIPATION AND JUNCTION TEMPERATURE section. Replaced paragraph " While it is recommended..." ..... 16</li> </ul>                                                                                                                                                                                                                                                                   |      |

**Changes from Revision E (April 2012) to Revision F**
**Page**

|                                                                                                                                                       |    |
|-------------------------------------------------------------------------------------------------------------------------------------------------------|----|
| • Added device TPS20xxC-2 .....                                                                                                                       | 1  |
| • Changed Feature From: Output Discharge When TPS20XXC is Disabled To: Selected parts with (TPS20xxC) and without (TPS20xxC-2) Output Discharge ..... | 1  |
| • Added devices TPS2041C, TPS2061C, TPS2065C-2, TPS2068C, and TPS2069C-2 to <a href="#">Table 1</a> and removed Product Preview .....                 | 1  |
| • Added the TPS2069C-2 Device .....                                                                                                                   | 1  |
| • Added devices TPS2041C, TPS2061C, TPS2065C-2, TPS2068C, and TPS2069C-2 to the Device Information table .....                                        | 2  |
| • Added PXKI in the DEVICE INFORMATION table SOT23-5 (DBV) column (TPS2069C) .....                                                                    | 2  |
| • Added Note 1 to the RECOMMENDED OPERATING CONDITIONS table .....                                                                                    | 3  |
| • Added TPS2041C, TPS2061C, TPS2068C, TPS2065C-2 and TPS2069C-2 devices to $I_{OUT}$ in the RECOMMENDED OPERATING CONDITIONS table .....              | 3  |
| • Added the DBV option to Power Switch $R_{DS(on)}$ 1.5 A rated output, 25°C mΩ .....                                                                 | 3  |
| • Added the DBV option to Power Switch $R_{DS(on)}$ 1.5 A rated output .....                                                                          | 3  |
| • Changed $I_{SO}$ Current Limit .....                                                                                                                | 3  |
| • Added Leakage Current .....                                                                                                                         | 3  |
| • Added the DBV option to Power Switch $R_{DS(on)}$ 1.5 A rated output . .....                                                                        | 4  |
| • Changed $I_{SO}$ Current Limit .....                                                                                                                | 4  |
| • Added Leakage Current .....                                                                                                                         | 5  |
| • Changed the second para graph of the ENABLE section .....                                                                                           | 14 |
| • Added sentence to end of paragraph in the OUTPUT DISCHARGE section .....                                                                            | 15 |

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type      | Package<br>Drawing | Pins | Package Qty | Eco Plan<br>(2)            | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|------------------|---------------|-------------------|--------------------|------|-------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TPS2000CDGK      | ACTIVE        | VSSOP             | DGK                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXFI                     | <a href="#">Samples</a> |
| TPS2000CDGKR     | ACTIVE        | VSSOP             | DGK                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXFI                     | <a href="#">Samples</a> |
| TPS2000CDGN      | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | BCMS                     | <a href="#">Samples</a> |
| TPS2000CDGNR     | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | BCMS                     | <a href="#">Samples</a> |
| TPS2001CDGK      | ACTIVE        | VSSOP             | DGK                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXGI                     | <a href="#">Samples</a> |
| TPS2001CDGKR     | ACTIVE        | VSSOP             | DGK                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXGI                     | <a href="#">Samples</a> |
| TPS2001CDGN      | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VBWQ                     | <a href="#">Samples</a> |
| TPS2001CDGNR     | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VBWQ                     | <a href="#">Samples</a> |
| TPS2041CDBVR     | ACTIVE        | SOT-23            | DBV                | 5    | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PYJI                     | <a href="#">Samples</a> |
| TPS2041CDBVT     | ACTIVE        | SOT-23            | DBV                | 5    | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PYJI                     | <a href="#">Samples</a> |
| TPS2051CDBVR     | ACTIVE        | SOT-23            | DBV                | 5    | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VBVQ                     | <a href="#">Samples</a> |
| TPS2051CDBVT     | ACTIVE        | SOT-23            | DBV                | 5    | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VBVQ                     | <a href="#">Samples</a> |
| TPS2061CDBVR     | ACTIVE        | SOT-23            | DBV                | 5    | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PXLI                     | <a href="#">Samples</a> |
| TPS2061CDBVT     | ACTIVE        | SOT-23            | DBV                | 5    | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PXLI                     | <a href="#">Samples</a> |
| TPS2061CDGN      | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXMI                     | <a href="#">Samples</a> |
| TPS2061CDGNR     | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXMI                     | <a href="#">Samples</a> |
| TPS2065CDBVR     | ACTIVE        | SOT-23            | DBV                | 5    | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VCAQ                     | <a href="#">Samples</a> |

| Orderable Device | Status<br>(1) | Package Type      | Package<br>Drawing | Pins | Package Qty | Eco Plan<br>(2)            | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|------------------|---------------|-------------------|--------------------|------|-------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TPS2065CDBVR-2   | ACTIVE        | SOT-23            | DBV                | 5    | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PYQI                     | <a href="#">Samples</a> |
| TPS2065CDBVT     | ACTIVE        | SOT-23            | DBV                | 5    | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VCAQ                     | <a href="#">Samples</a> |
| TPS2065CDBVT-2   | ACTIVE        | SOT-23            | DBV                | 5    | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PYQI                     | <a href="#">Samples</a> |
| TPS2065CDGN      | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VCAQ                     | <a href="#">Samples</a> |
| TPS2065CDGN-2    | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PYRI                     | <a href="#">Samples</a> |
| TPS2065CDGNR     | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VCAQ                     | <a href="#">Samples</a> |
| TPS2065CDGNR-2   | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PYRI                     | <a href="#">Samples</a> |
| TPS2068CDGN      | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXNI                     | <a href="#">Samples</a> |
| TPS2068CDGNR     | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PXNI                     | <a href="#">Samples</a> |
| TPS2069CDBVR     | ACTIVE        | SOT-23            | DBV                | 5    | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PYKI                     | <a href="#">Samples</a> |
| TPS2069CDBVT     | ACTIVE        | SOT-23            | DBV                | 5    | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | PYKI                     | <a href="#">Samples</a> |
| TPS2069CDGN      | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VBUQ                     | <a href="#">Samples</a> |
| TPS2069CDGN-2    | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 80          | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PYSI                     | <a href="#">Samples</a> |
| TPS2069CDGNR     | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | VBUQ                     | <a href="#">Samples</a> |
| TPS2069CDGNR-2   | ACTIVE        | MSOP-<br>PowerPAD | DGN                | 8    | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAUAG      | Level-2-260C-1 YEAR  | -40 to 85    | PYSI                     | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

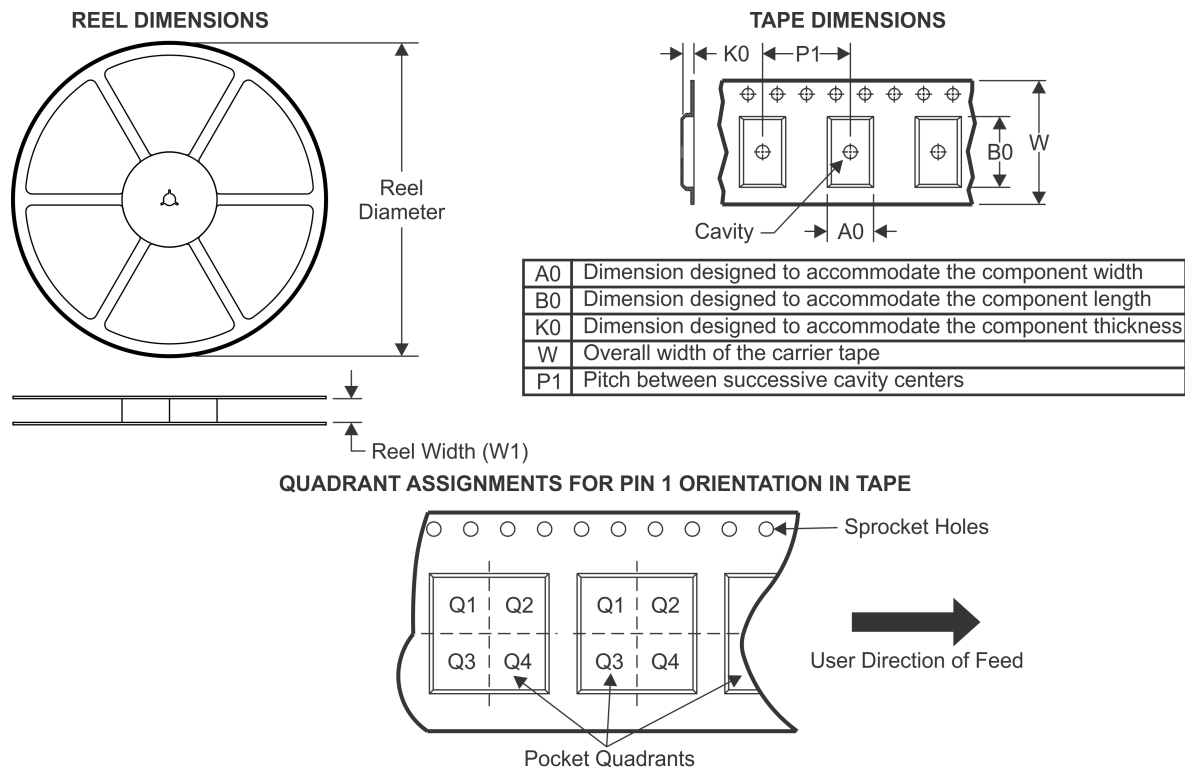
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.

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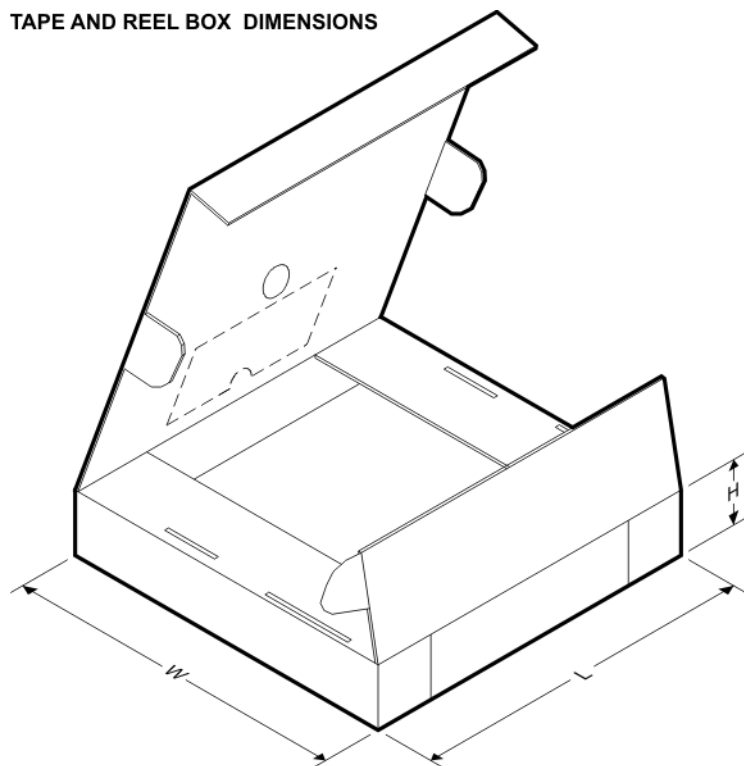
**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device       | Package Type   | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|----------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS2000CDGKR | VSSOP          | DGK             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2000CDGNR | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2000CDGNR | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.3     | 1.3     | 8.0     | 12.0   | Q1            |
| TPS2001CDGKR | VSSOP          | DGK             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2001CDGNR | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2001CDGNR | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.3     | 1.3     | 8.0     | 12.0   | Q1            |
| TPS2041CDBVR | SOT-23         | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| TPS2051CDBVR | SOT-23         | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| TPS2061CDBVR | SOT-23         | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| TPS2061CDGNR | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2065CDBVR | SOT-23         | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |

| Device         | Package Type   | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|----------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS2065CDBVR-2 | SOT-23         | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| TPS2065CDGNR   | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2065CDGNR-2 | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2068CDGNR   | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2069CDBVR   | SOT-23         | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| TPS2069CDGNR   | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| TPS2069CDGNR   | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.3     | 1.3     | 8.0     | 12.0   | Q1            |
| TPS2069CDGNR-2 | MSOP-Power PAD | DGN             | 8    | 2500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS

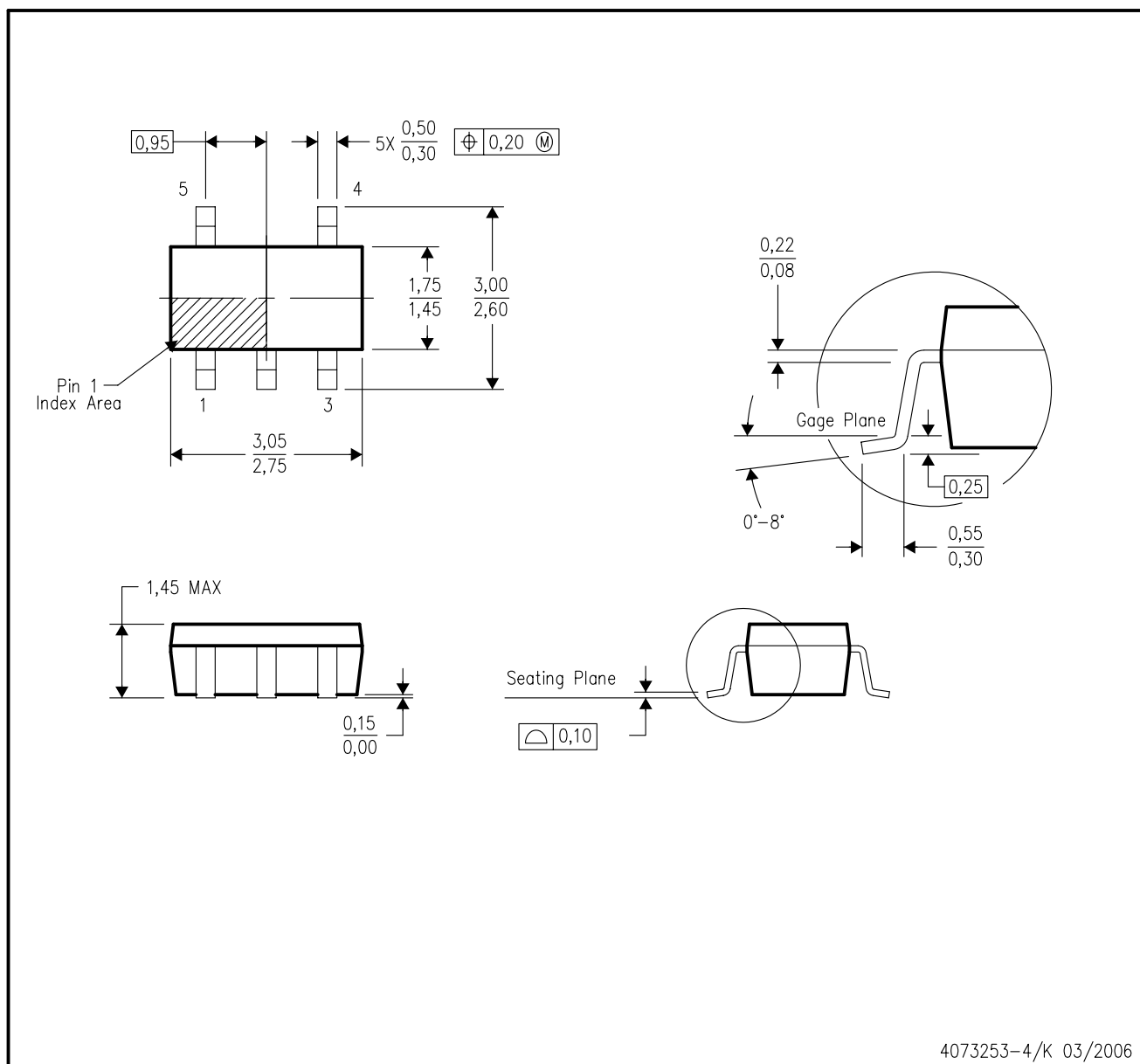


\*All dimensions are nominal

| Device         | Package Type  | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|----------------|---------------|-----------------|------|------|-------------|------------|-------------|
| TPS2000CDGKR   | VSSOP         | DGK             | 8    | 2500 | 366.0       | 364.0      | 50.0        |
| TPS2000CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 360.0       | 162.0      | 98.0        |
| TPS2000CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 370.0       | 355.0      | 55.0        |
| TPS2001CDGKR   | VSSOP         | DGK             | 8    | 2500 | 366.0       | 364.0      | 50.0        |
| TPS2001CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 360.0       | 162.0      | 98.0        |
| TPS2001CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 370.0       | 355.0      | 55.0        |
| TPS2041CDBVR   | SOT-23        | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| TPS2051CDBVR   | SOT-23        | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| TPS2061CDBVR   | SOT-23        | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| TPS2061CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 366.0       | 364.0      | 50.0        |
| TPS2065CDBVR   | SOT-23        | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| TPS2065CDBVR-2 | SOT-23        | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| TPS2065CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 360.0       | 162.0      | 98.0        |
| TPS2065CDGNR-2 | MSOP-PowerPAD | DGN             | 8    | 2500 | 366.0       | 364.0      | 50.0        |
| TPS2068CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 366.0       | 364.0      | 50.0        |
| TPS2069CDBVR   | SOT-23        | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| TPS2069CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 360.0       | 162.0      | 98.0        |
| TPS2069CDGNR   | MSOP-PowerPAD | DGN             | 8    | 2500 | 370.0       | 355.0      | 55.0        |
| TPS2069CDGNR-2 | MSOP-PowerPAD | DGN             | 8    | 2500 | 366.0       | 364.0      | 50.0        |

## DBV (R-PDSO-G5)

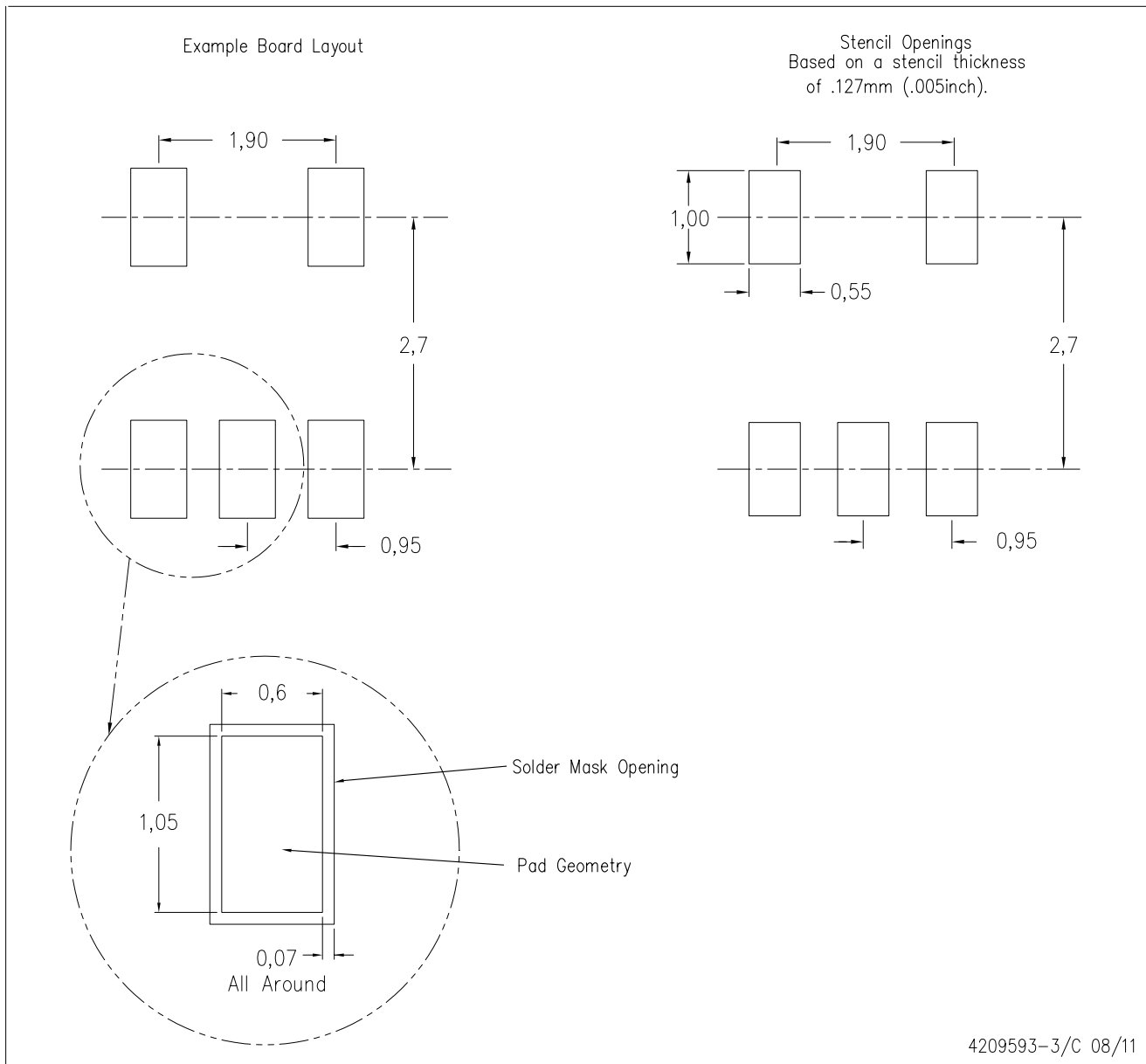
## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

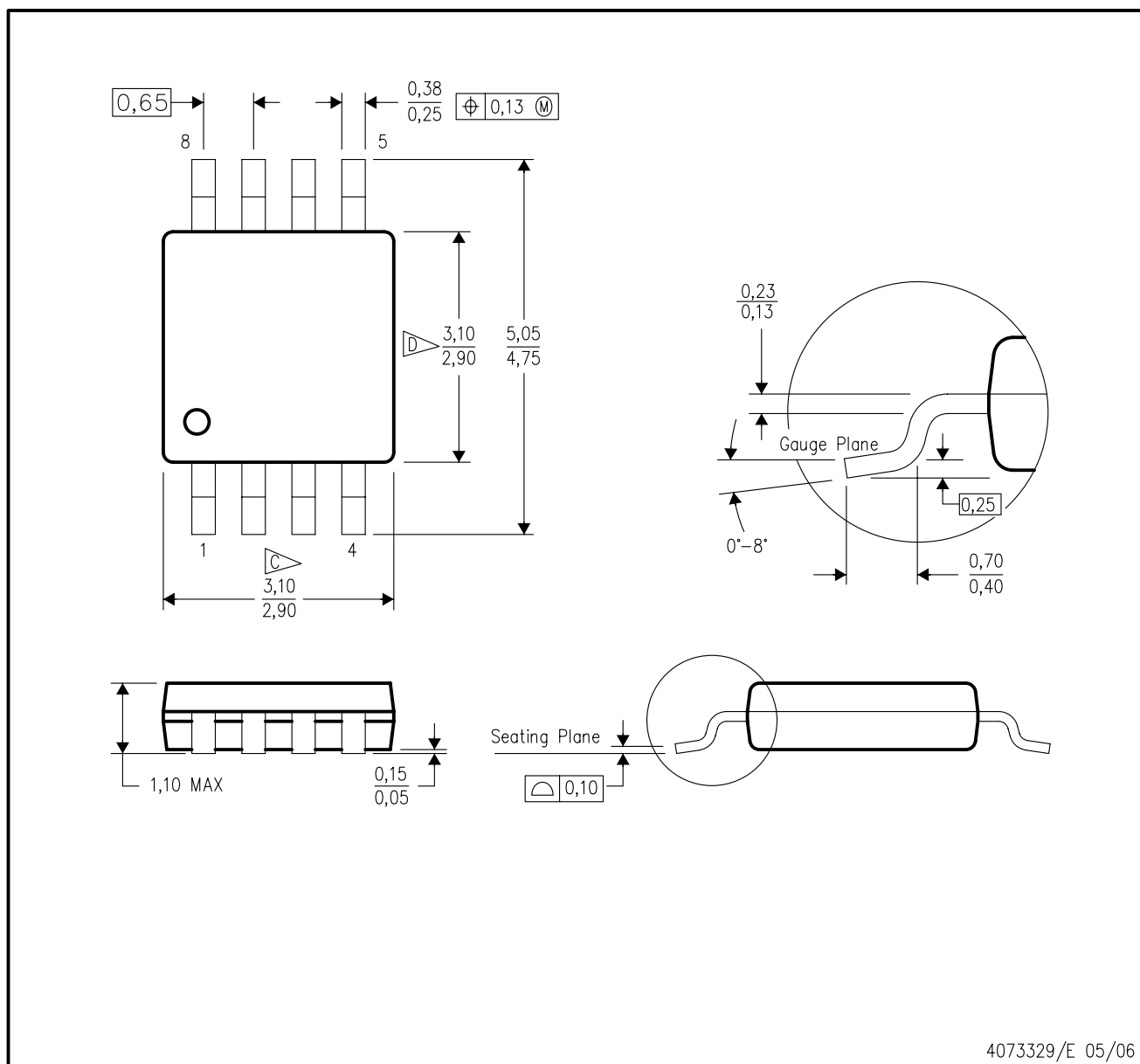
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DGK (S-PDSO-G8)

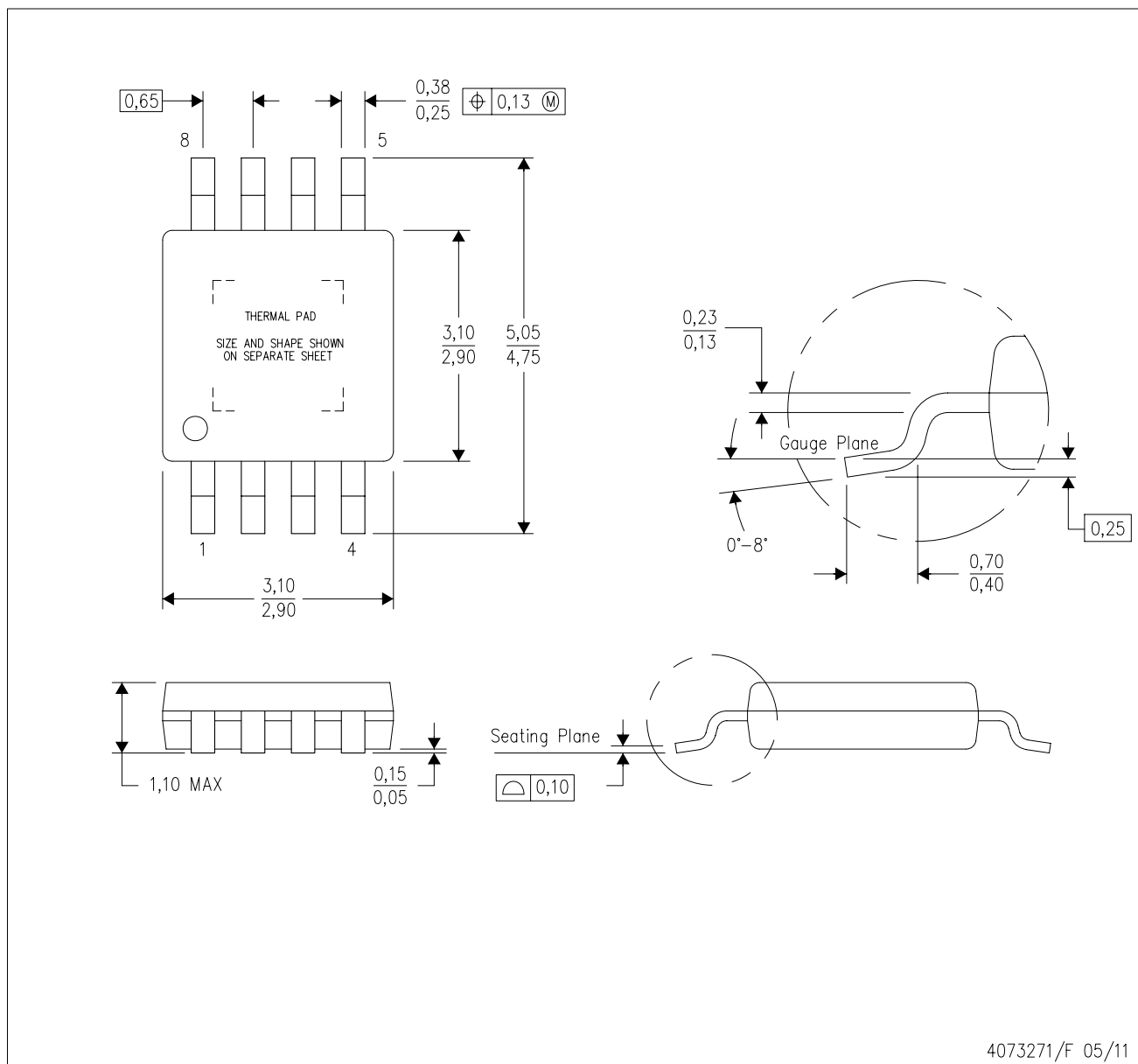
PLASTIC SMALL-OUTLINE PACKAGE



4073329/E 05/06

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - Falls within JEDEC MO-187 variation AA-T

PowerPAD is a trademark of Texas Instruments.

DGN (S-PDSO-G8)

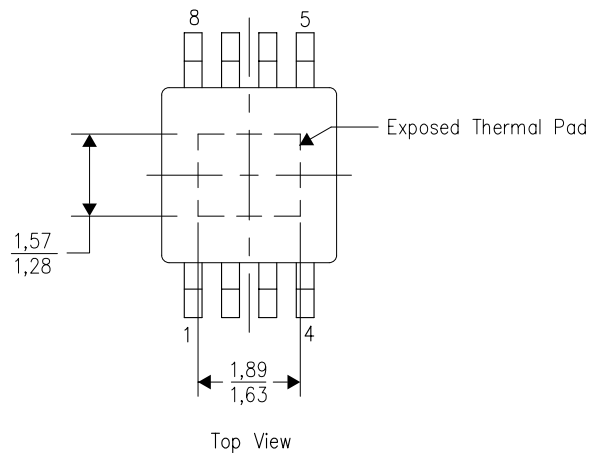
PowerPAD™ PLASTIC SMALL OUTLINE

## THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

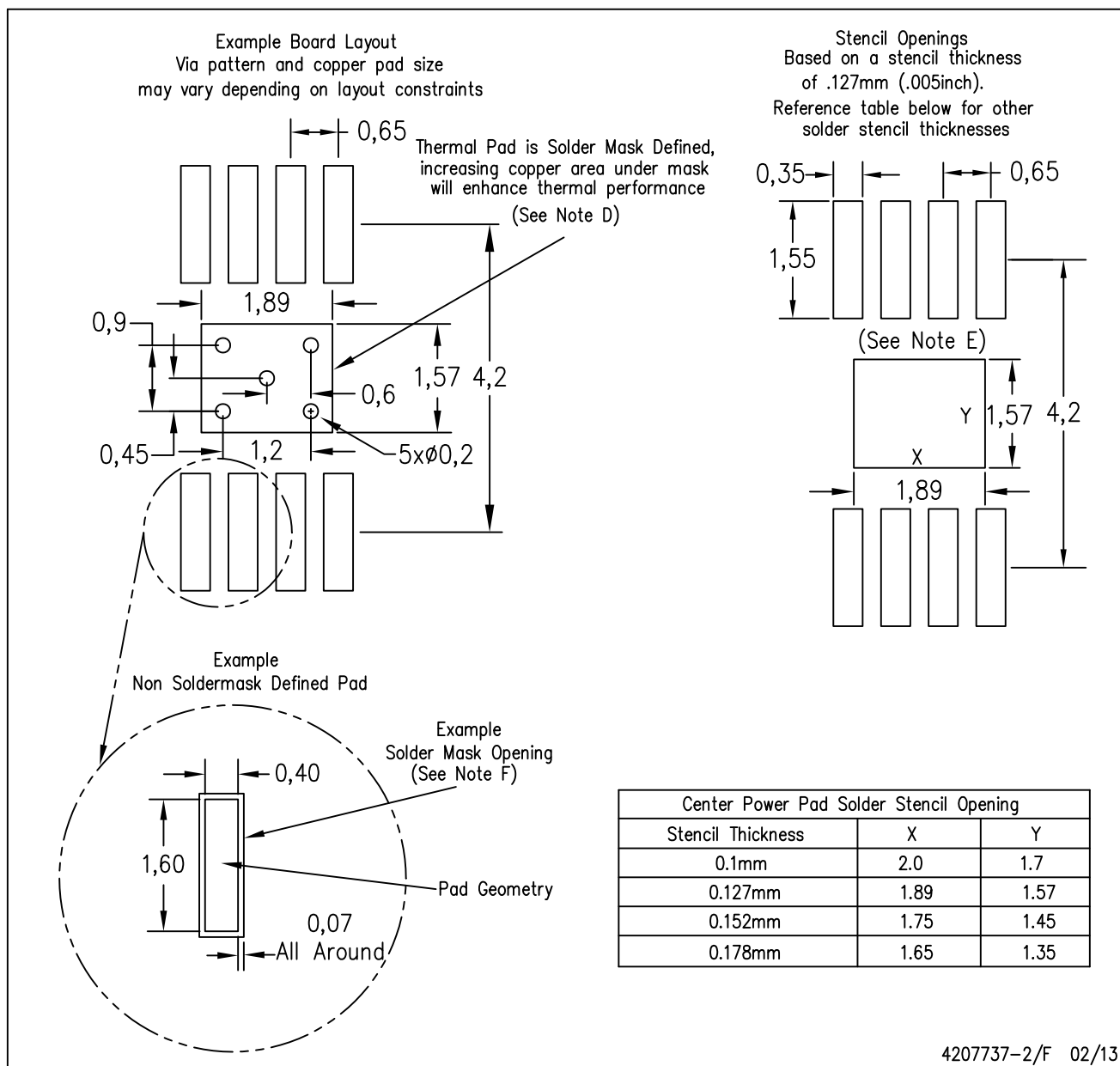
4206323-2/1 12/11

NOTE: All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

DGN (R-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PowerPAD is a trademark of Texas Instruments

DGN (S-PDSO-G8)

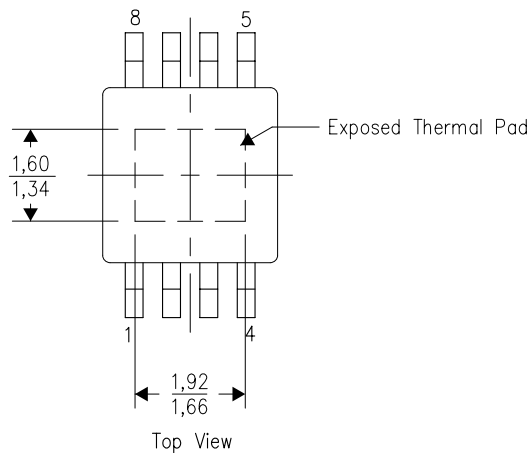
PowerPAD™ PLASTIC SMALL OUTLINE

## THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

4206323-4/1 12/11

NOTE: All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

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|                               |                                                                                          |
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| Industrial                    | <a href="http://www.ti.com/industrial">www.ti.com/industrial</a>                         |
| Medical                       | <a href="http://www.ti.com/medical">www.ti.com/medical</a>                               |
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